



MPU-3000/MPU-3050 Motion Processing Unit Product Specification Rev 2.5



CONTENTS

1	DOCUMENT INFORMATION.....	4
1.1	REVISION HISTORY	4
1.2	PURPOSE AND SCOPE.....	5
1.3	PRODUCT OVERVIEW	5
1.4	APPLICATIONS	6
2	FEATURES.....	7
2.1	SENSORS.....	7
2.2	DIGITAL OUTPUT.....	7
2.3	MOTION PROCESSING	7
2.4	CLOCKING	7
2.5	POWER	7
2.6	PACKAGE.....	8
3	ELECTRICAL CHARACTERISTICS	9
3.1	SENSOR SPECIFICATIONS	9
3.2	ELECTRICAL SPECIFICATIONS.....	10
3.3	ELECTRICAL SPECIFICATIONS, CONTINUED	11
3.4	ELECTRICAL SPECIFICATIONS, CONTINUED	12
3.5	I ² C TIMING CHARACTERIZATION.....	13
3.6	SPI TIMING CHARACTERIZATION (MPU-3000 ONLY)	14
3.7	ABSOLUTE MAXIMUM RATINGS.....	15
4	APPLICATIONS INFORMATION	16
4.1	PIN OUT AND SIGNAL DESCRIPTION	16
4.2	TYPICAL OPERATING CIRCUITS	17
4.3	BILL OF MATERIALS FOR EXTERNAL COMPONENTS	17
4.4	RECOMMENDED POWER-ON PROCEDURE	18
5	FUNCTIONAL OVERVIEW.....	19
5.1	BLOCK DIAGRAM	19
5.2	OVERVIEW	19
5.3	THREE-AXIS MEMS GYROSCOPE WITH 16-BIT ADCs AND SIGNAL CONDITIONING	19
5.4	DIGITAL MOTION PROCESSOR	20
5.5	PRIMARY I ² C AND SPI SERIAL COMMUNICATIONS INTERFACES	20
5.6	SECONDARY I ² C SERIAL INTERFACE (FOR A THIRD-PARTY ACCELEROMETER)	20
6	CLOCKING.....	21
6.1	INTERNAL CLOCK GENERATION	21
6.2	CLOCK OUTPUT	21
6.3	SENSOR DATA REGISTERS	21
6.4	FIFO	21
6.5	INTERRUPTS	21
6.6	DIGITAL-OUTPUT TEMPERATURE SENSOR	22
6.7	BIAS AND LDO.....	22
6.8	CHARGE PUMP	22
6.9	CHIP VERSION	22
7	DIGITAL INTERFACE	23
7.1	I ² C AND SPI (MPU-3000 ONLY) SERIAL INTERFACES	23
8	SERIAL INTERFACE CONSIDERATIONS (MPU-3050).....	28



MPU-3000/MPU-3050 Product Specification

Document Number: PS-MPU-3000A-00
Revision: 2.5
Release Date: 12/23/2010

8.1	MPU-3050 SUPPORTED INTERFACES	28
8.2	LOGIC LEVELS	28
9	ASSEMBLY	31
9.1	ORIENTATION	31
9.2	PCB LAYOUT GUIDELINES	32
9.3	TRACE ROUTING	34
9.4	COMPONENT PLACEMENT	34
9.5	PCB MOUNTING AND CROSS-AXIS SENSITIVITY	35
9.6	MEMS HANDLING INSTRUCTIONS	36
9.7	ESD CONSIDERATIONS	36
9.8	GYROSCOPE SURFACE MOUNT GUIDELINES	36
9.9	REFLOW SPECIFICATION	37
9.10	STORAGE SPECIFICATIONS	38
9.11	PACKAGE MARKING SPECIFICATION	39
9.12	TAPE & REEL SPECIFICATION	39
9.13	LABEL	41
9.14	PACKAGING	41
10	RELIABILITY	42
10.1	QUALIFICATION TEST POLICY	42
10.2	QUALIFICATION TEST PLAN	42
11	ENVIRONMENTAL COMPLIANCE	43



1 Document Information

1.1 Revision History

Revision Date	Revision	Description
6/25/09	1.0	Initial Release
9/28/09	2.0	Changes for revision level compliance of MPU-30X0 to MPU-3000 specification: Sec. 1.2 Added Revision B1 silicon note Sec. 1.3 Updated noise specification to 0.03°/s/√Hz Sec. 2.3 Added secondary I ² C interface Sec. 3.1 Updated sensor specifications table Sec. 3.2 Changed VDD to 2.5V and T _A = 25°C Sec. 3.2-3.3 Changed electrical specifications table format and typical values Sec. 4.1 Updated pin-out and signal descriptions with new diagram Sec. 4.2 Updated typical operating circuit diagram Sec. 5.1 Updated new block diagram descriptions for primary and secondary I ² C serial interfaces Sec. 5.9 Changed FIFO description Sec. 6 Edited digital interface Sec. 10.2 Updated package drawing/dimensions Sec. 10.7 Edited trace routing Sec. 13 Added Appendix 1.0 Errata for Revision G devices
11/5/09	2.1	Sec. 10 Added Material Handling Specification content to this section
12/23/09	2.2	Sec. 3.2 Updated Electrical Specifications with Power-supply ramp rate for VLOGIC Reference Voltage Sec. 3.3 Updated Level Output Current specifications for the Primary and Secondary I2C interfaces Sec. 3.4 Updated Frequency Variation Over Temperature specification for internal clock source Sec. 3.5.1 Updated ESD specification Sec. 4.4 Added recommended power-on procedure diagram
3/15/2010	2.3	Sec 1.4 Added new InvenSense trademarks under Applications Sec 2.2 Edited Digital Output for 400KHz standard (not up to) Sec 3.1 Changed Sensitivity Scale Factor to 115 LSB/(°/s) Sec 4.4 Updated Recommended Power-on Procedure diagram Sec 8.2 Modified Example Power Configuration diagram to remove IME-3000 reference Sec 11.2 Updated ESD-HBM for Device Component Level Tests Removed all references to IME-3000 and replaced with third-party accelerometer.
8/17/2010	2.4	Section 3.1, updated sensitivity scale factor, ZRO, Noise performance Section 3.2, added operating current for without DMP case, added start-up time Updated table in section 8.2 with reference to AUX_VDDIO Added section 9.1 Demo Software Added sections 10 (Register Maps) and 11 (Register Description) Updated text and table in section 12.9 Added section 12.11 Storage Specifications Created a new section 14 for Environment Compliance
8/26/2010	2.4b	Updated specifications for C _i in section 3.2, section 3.3, C _b in section 3.5 Updated V _{IH} and V _{hys} for section 3.3
12/23/2010	2.5	Created a separate document for Register Information & removed MPL section



1.2 Purpose and Scope

This document is a product specification, providing a description, specifications, and design related information for the MPU-3000™ and MPU-3050™ Motion Processing Unit™ (collectively called the MPU-30X0™). References [1], [2] and [3] provide a complementary set of software guides for the Motion Processing Library (MPL) and describe in detail the API and System Layer routines needed for interfacing to the MPU-30X0.

Electrical characteristics are based upon simulation results and limited characterization data of advanced samples only. Specifications are subject to change without notice. Final specifications will be updated based upon characterization of final silicon.

1.3 Product Overview

The MPU-30X0 Motion Processing Unit (MPU™) is the world's first motion processing solution with integrated 6-axis sensor fusion for smart phone applications. The MPU-30X0 has an embedded 3-axis gyroscope and Digital Motion Processor™ (DMP) hardware accelerator engine with a secondary I²C port that interfaces to third party digital accelerometers to deliver a complete 6-axis sensor fusion output to its primary I²C or SPI port. This combines both linear and rotational motion into a single data stream for the application. This breakthrough in gyroscope technology provides a dramatic 68% smaller footprint, 40% thinner package, consumes 55% less power, and has inherent cost advantages compared to the latest competitive gyro solutions to uniquely address the fast-growing demand for 6-axis motion processing in mobile handsets.

The MPU-30X0 significantly extends and transforms motion sensing features provided by accelerometers beyond portrait and landscape orientation, to motion processing functionality. The MPU measures and processes both linear and rotational movements, creating a higher degree of 1:1 motion interactivity between the user and their handset. Similar to the proliferation of Bluetooth, camera phone image sensors and Wi-Fi, motion processing is becoming a “must-have” function in mobile handsets benefitting wireless carriers, mobile handset OEMs, application developers and end-users. By providing an integrated sensor fusion output, the DMP in the MPU-30X0 offloads the intensive motion processing computation requirements from the applications processor, reducing the need for frequent polling of the motion sensor output and enabling use of low cost, low power application processors thereby increasing overall battery life of handsets. Since handsets today are of multi-function nature, MPU-30X0 not only provides accurate 1:1 motion tracking for some of the more common applications such as still/video image stabilization, gaming and dead reckoning, the 32-bit DMP can be programmed to deliver advanced UI, e.g. multiple kinds of gestures and character recognition leading to applications such as *Airsign™*, *TouchAnywhere™*, *MotionCommand™*.

By leveraging its patented and volume-proven Nasiri-Fabrication platform, which integrates MEMS wafers with companion CMOS electronics through wafer-level bonding, InvenSense has driven the MPU-30X0 package size down to a revolutionary footprint of 4x4x0.9mm (QFN), while providing the highest performance, lowest noise, and the lowest cost semiconductor packaging to address a wide range of handheld consumer electronic devices.

The MPU-30X0 integrates 16-bit analog-to-digital converters (ADCs), selectable low-pass filters, FIFO, embedded temperature sensor, and Fast Mode I²C or SPI (MPU-3000 only) interfaces. Performance features include programmable full-scale range from ± 250 degrees-per-second up to ± 2000 degrees-per-second (°/s or dps), and low-noise of 0.01°/s/√Hz, while providing the highest robustness supporting 10,000g shock in operation. The highest cross-axis isolation is achieved by design from its single silicon integration. Factory-calibrated initial sensitivity reduces production-line calibration requirements. The part's on-chip FIFO and dedicated I²C-master accelerometer sensor

MPL Software References

- [1] MPL Programmer's Guide – Application Note (AN-MPL-3000-UG-01 or later)
- [2] MPL Functional Specification (DOC-MPL-FS-V2.3 or later)
- [3] MPL Product Specification (PS-MPL-3000-v2.0 or later)



bus simplify system timing and lower system power consumption. The sensor bus allows the MPU-30X0 to directly acquire data from the off-chip accelerometer without intervention from an external processor. Other industry-leading features include a small 4mmx4mmx0.9mm plastic QFN package, an embedded temperature sensor, programmable interrupts, and a low 13mW power consumption. Parts are available with I2C and SPI serial interfaces, a VDD operating range of 2.1 to 3.6V, and a VLOGIC interface voltage from 1.71V to 3.6V.

The MPU-3000 and MPU-3050 are identical, except that the MPU-3050 supports the I²C serial interface only, and has a separate VLOGIC reference pin (in addition to its analog supply pin, VDD), which sets the logic levels of its I²C interface. The VLOGIC voltage may be between 1.71V min to VDD max. The MPU-3000 supports both I²C and SPI interfaces and has a single supply pin, VDD, which is the device's logic reference supply and the analog supply for the part. The table below outlines these differences:

Primary Differences between MPU-3000 and MPU-3050

Part / Item	MPU-3000	MPU-3050
VDD	2.1V to 3.6V	2.1V to 3.6V
VLOGIC	n/a	1.71V to VDD
Serial Interfaces Supported	I ² C, SPI	I ² C
Pin 8	/CS	VLOGIC
Pin 9	AD0/SDO	AD0
Pin 23	SCL/SCLK	SCL
Pin 24	SDA/SDI	SDA

1.4 Applications

- *BlurFree*[™] technology (for Video/Still Image Stabilization)
- *AirSign*[™] technology (for Security/Authentication)
- *TouchAnywhere*[™] technology (for Application Control/Navigation)
- *MotionCommand*[™] technology (for Gesture Short-cuts)
- Motion-enabled game and application framework
- InstantGesture[™] iG[™] gesture recognition
- "No Touch" UI
- Handset gaming
- Location based services, points of interest, and dead reckoning
- Improved camera image quality through image stabilization
- Health and sports monitoring
- Power management



2 Features

The MPU-30X0 Motion Processing Unit includes a wide range of features:

2.1 Sensors

- X-, Y-, Z-Axis angular rate sensors (gyros) on one integrated circuit
- Digital-output temperature sensor
- External sync signal connected to the FSYNC pin supports image, video and GPS synchronization
- 6-axis motion processing capability using secondary I²C interface to directly connect to a digital 3-axis third-party accelerometer
- Factory calibrated scale factor
- High cross-axis isolation via proprietary MEMS design
- 10,000g shock tolerant

2.2 Digital Output

- Fast Mode (400kHz) I²C or 1MHz SPI (MPU-3000 only) serial interfaces
- 16-bit ADCs for digitizing sensor outputs
- Angular rate sensors (gyros) with applications-programmable full-scale-range of $\pm 250^\circ/\text{sec}$, $\pm 500^\circ/\text{sec}$, $\pm 1000^\circ/\text{sec}$, or $\pm 2000^\circ/\text{sec}$.

2.3 Motion Processing

- Embedded Digital Motion Processing™ (DMP™) engine supports 3D motion processing and gesture recognition algorithms
- When used together with a digital 3-axis third party accelerometer, the MPU-30X0 collects the accelerometer data via a dedicated interface, while synchronizing data sampling at a user defined rate. The total data set obtained by the MPU-30X0 includes 3-axis gyroscope data and 3-axis accelerometer data, temperature data, and the one bit external sync signal connected to the FSYNC pin. The MPU also downloads the results calculated by the digital 3-axis third party accelerometer internal registers.
- FIFO buffers complete data set, reducing timing requirements on the system processor and saving power by letting the processor burst read the FIFO data, and then go into a low-power sleep mode while the MPU collects more data.
- Programmable interrupt supports features such as gesture recognition, panning, zooming, scrolling, zero-motion detection, tap detection, and shake detection
- Hand jitter filter
- Programmable low-pass filters
- Feature extraction for peak and zero-crossing detection
- Pedometer functionality

2.4 Clocking

- On-chip timing generator clock frequency $\pm 2\%$ over full temperature range
- Optional external clock inputs of 32.768kHz or 19.2MHz
- 1MHz clock output to synchronize with digital 3-axis accelerometer

2.5 Power

- VDD supply voltage range of 2.1V to 3.6V
- Flexible VLOGIC reference voltage allows for multiple I2C interface voltage levels (MPU-3050 only)
- Power consumption with all three axis and DMP active: 6.1mA
- Sleep mode: 5 μ A
- Each axis can be individually powered down



2.6 Package

- 4x4x0.9mm QFN plastic package
- MEMS structure hermetically sealed and bonded at wafer level
- RoHS and Green compliant



3 Electrical Characteristics

3.1 Sensor Specifications

Typical Operating Circuit of Section 4.2, VDD = 2.5V, VLOGIC = 2.5V (MPU-3050 Only), T_A=25°C.

Parameter	Conditions	Min	Typical	Max	Unit	Notes
GYRO SENSITIVITY						
Full-Scale Range	FS_SEL=0		±250		°/s	4, 7
	FS_SEL=1		±500			4, 7
	FS_SEL=2		±1000			4, 7
	FS_SEL=3		±2000			4, 7
Gyro ADC Word Length			16		Bits	3
Sensitivity Scale Factor	FS_SEL=0		131		LSB/(°/s)	1
	FS_SEL=1		65.5			3
	FS_SEL=2		32.8			3
	FS_SEL=3		16.4			3
Sensitivity Scale Factor Tolerance	25°C	-6	±2	+6	%	1
Sensitivity Scale Factor Variation Over Temperature	-40°C to +85°C		±2		%	8
Nonlinearity	Best fit straight line; 25°C		0.2		%	6
Cross-Axis Sensitivity			2		%	6
GYRO ZERO-RATE OUTPUT (ZRO)						
Initial ZRO Tolerance	25°C		±20		°/s	1
ZRO Variation Over Temperature	-40°C to +85°C		±0.03		°/s/°C	8
Power-Supply Sensitivity (1-10Hz)	Sine wave, 100mVpp; VDD=2.2V		0.2		°/s	5
Power-Supply Sensitivity (10 - 250Hz)	Sine wave, 100mVpp; VDD=2.2V		0.2		°/s	5
Power-Supply Sensitivity (250Hz - 100kHz)	Sine wave, 100mVpp; VDD=2.2V		4		°/s	5
Linear Acceleration Sensitivity	Static		0.1		°/s/g	6
GYRO NOISE PERFORMANCE						
Total RMS Noise	FS_SEL=0 DLPFCFG=2 (100Hz)		0.1		°/s-rms	1
Low-frequency RMS noise	Bandwidth 1Hz to 10Hz		0.033		°/s-rms	1
Rate Noise Spectral Density	At 10Hz		0.01		°/s/√Hz	3
GYRO MECHANICAL FREQUENCIES						
X-Axis		30	33	36	kHz	1
Y-Axis		27	30	33	kHz	1
Z-Axis		24	27	30	kHz	1
GYRO START-UP TIME						
ZRO Settling	DLPFCFG=0 to ±1°/s of Final		50		ms	5
TEMPERATURE SENSOR						
Range			-30 to 85		°C	2
Sensitivity	Untrimmed		280		LSB/°C	2
Room-Temperature Offset	35°C		-13200		LSB	1
Linearity	Best fit straight line (-30°C to +85°C)		±1		°C	2
TEMPERATURE RANGE						
Specified Temperature Range		-40		85	°C	2

Notes:

1. Tested in production
2. Based on characterization of 30 parts over temperature on evaluation board or in socket
3. Based on design, through modeling and simulation across PVT
4. Typical. Randomly selected part measured at room temperature on evaluation board or in socket
5. Based on characterization of 5 parts over temperature
6. Tested on 20 parts at room temperature
7. Part is characterized to Full-Scale Range. Maximum ADC output is $[2^{16} / (\text{Sensitivity} \times 2)]$
Example: For Sensitivity of 131 LSB/(°/s), $[2^{16} / (131 \times 2)] = \pm 250$ °/s.
8. Based on characterization of 48 parts on evaluation board or in socket



MPU-3000/MPU-3050 Product Specification

Document Number: PS-MPU-3000A-00
Revision: 2.5
Release Date: 12/23/2010

3.2 Electrical Specifications

Typical Operating Circuit of Section 4.2, VDD = 2.5V, VLOGIC = 2.5V (MPU-3050 only), T_A = 25°C.

Parameters	Conditions	Min	Typical	Max	Units	Notes
VDD POWER SUPPLY						
Operating Voltage Range	Monotonic ramp. Ramp rate is 10% to 90% of the final value (see Figure in Section 4.4)	2.1		3.6	V	2
Power-Supply Ramp Rate		0		5	ms	2
Normal Operating Current			6.1 5.9		mA mA	1
Sleep Mode Current	DMP disabled		5		μA	4
VLOGIC REFERENCE VOLTAGE (must be regulated)						
Voltage Range	VLOGIC must be ≤VDD at all times	1.71		VDD	V	3, 5
Power-Supply Ramp Rate	Monotonic ramp. Ramp rate is 10% to 90% of the final value (see Figure in Section 4.4)			1	ms	
Normal Operating Current	Does not include pull up resistor current draw as that is system dependent		100		μA	
START-UP TIME FOR REGISTER READ/WRITE			20	100	ms	4
I²C ADDRESS	AD0 = 0 AD0 = 1		1101000 1101001			1
DIGITAL INPUTS (SDI, SCLK, FSYNC, AD0, /CS, CLKIN)						
V _{IH} , High Level Input Voltage		0.7*VDD		0.3*VDD	V	4
V _{IL} , Low Level Input Voltage					V	4
C _i , Input Capacitance					pF	
DIGITAL OUTPUT (INT)	For MPU-3050 only					
V _{OH} , High Level Output Voltage	R _{LOAD} =1MΩ	0.9*VLOGIC		0.1*VLOGIC 0.1	V	2
V _{OL1} , LOW-Level Output Voltage	R _{LOAD} =1MΩ				V	2
V _{OL,INT1} , INT Low-Level Output Voltage	OPEN=1, 0.3mA sink current				V	2
Output Leakage Current	OPEN=1		100		nA	3
t _{INT} , INT Pulse Width	LATCH_INT_EN=0		50		μs	3

Notes:

1. Tested in production
2. Based on characterization of 30 parts over temperature on evaluation board or in socket
3. Typical. Randomly selected part measured at room temperature on evaluation board or in socket
4. Based on characterization of 5 parts over temperature
5. Refer to Section 4.4 for the recommended power-on procedure

**3.3 Electrical Specifications, continued**Typical Operating Circuit of Section 4.2, VDD = 2.5V, VLOGIC = 2.5V (MPU-3050 only), T_A=25°C.

Parameters	Conditions	Typical	Units	Notes
Primary I²C I/O (SCL, SDA)				
V _{IL} , LOW-Level Input Voltage	MPU-3000	-0.5 to 0.3*VLOGIC	V	1
V _{IH} , HIGH-Level Input Voltage	MPU-3000	0.7*VLOGIC to VLOGIC + 0.5V	V	1
V _{hys} , Hysteresis	MPU-3000	0.1*VLOGIC	V	1
V _{IL} , LOW Level Input Voltage	MPU-3050	-0.5V to 0.3*VLOGIC	V	1
V _{IH} , HIGH-Level Input Voltage	MPU-3050	0.7*VLOGIC to VLOGIC + 0.5V	V	1
V _{hys} , Hysteresis	MPU-3050	0.1*VLOGIC	V	1
V _{OL1} , LOW-Level Output Voltage	3mA sink current	0 to 0.4	V	1
I _{OL} , LOW-Level Output Current	V _{OL} = 0.4V	3	mA	1
	V _{OL} = 0.6V	5	mA	1
Output Leakage Current		100	nA	2
t _{of} , Output Fall Time from V _{IHmax} to V _{ILmax}	C _b bus capacitance in pf	20+0.1C _b to 250	ns	1
C _i , Capacitance for Each I/O pin		< 10	pF	
Secondary I²C I/O (AUX_CL, AUX_DA)				
V _{IL} , LOW-Level Input Voltage	AUX_VDDIO=0 (MPU-3050)	-0.5V to 0.3*VLOGIC	V	1
V _{IH} , HIGH-Level Input Voltage		0.7*VLOGIC to VLOGIC + 0.5V	V	
V _{hys} , Hysteresis		0.1*VLOGIC	V	
V _{OL1} , LOW-Level Output Voltage	VLOGIC > 2V; 1mA sink current	0 to 0.4	V	1
V _{OL3} , LOW-Level Output Voltage	VLOGIC < 2V; 1mA sink current	0 to 0.2*VLOGIC	V	1
I _{OL} , LOW-Level Output Current	V _{OL} = 0.4V	1	mA	1
	V _{OL} = 0.6V	1	mA	1
Output Leakage Current		100	nA	2
t _{of} , Output Fall Time from V _{IHmax} to V _{ILmax}	C _b bus capacitance in pF	20+0.1C _b to 250	ns	1
C _i , Capacitance for Each I/O pin		< 10	pF	
Secondary I²C I/O (AUX_CL, AUX_DA)				
V _{IL} , LOW-Level Input Voltage	AUX_VDDIO=1	-0.5 to 0.3*VDD	V	1
V _{IH} , HIGH-Level Input Voltage		0.7*VDD to VDD+0.5V	V	1
V _{hys} , Hysteresis		0.1*VDD	V	
V _{OL1} , LOW-Level Output Voltage	1mA sink current	0 to 0.4	V	1
I _{OL} , LOW-Level Output Current	V _{OL} = 0.4V	1	mA	1
	V _{OL} = 0.6V	1	mA	1
Output Leakage Current		100	nA	2
t _{of} , Output Fall Time from V _{IHmax} to V _{ILmax}	C _b bus cap. in pF	20+0.1C _b to 250	ns	1
C _i , Capacitance for Each I/O pin		< 10	pF	

Notes:

1. Based on characterization of 5 parts over temperature.
2. Typical. Randomly selected part measured at room temperature on evaluation board or in socket

**3.4 Electrical Specifications, continued**Typical Operating Circuit of Section 4.2, VDD = 2.5V, VLOGIC = 2.5V (MPU-3050 only), T_A=25°C.

Parameters	Conditions	Min	Typical	Max	Units	Notes
INTERNAL CLOCK SOURCE						
Sample Rate, Fast	CLK_SEL=0,1,2,3 DLPFCFG=0 SAMPLERATEDIV = 0		8		kHz	3
Sample Rate, Slow	DLPFCFG=1,2,3,4,5, or 6 SAMPLERATEDIV = 0		1		kHz	3
Reference Clock Output	CLKOUTEN = 1		1.024		MHz	3
Clock Frequency Initial Tolerance	CLK_SEL=0, 25°C	-5		+5	%	1
	CLK_SEL=1,2,3; 25°C	-1		+1	%	1
Frequency Variation over Temperature	CLK_SEL=0		-15 to +10		%	2
	CLK_SEL=1,2,3		+/-1		%	2
PLL Settling Time	CLK_SEL=1,2,3		1		ms	
EXTERNAL 32.768kHz CLOCK						
External Clock Frequency	CLK_SEL=4		32.768		kHz	
External Clock Jitter	Cycle-to-cycle rms		1 to 2		μs	
Sample Rate, Fast	DLPFCFG=0 SAMPLERATEDIV = 0		8.192		kHz	
Sample Rate, Slow	DLPFCFG=1,2,3,4,5, or 6 SAMPLERATEDIV = 0		1.024		kHz	
Reference Clock Output	CLKOUTEN = 1		1.0486		MHz	
PLL Settling Time			1		ms	
EXTERNAL 19.2MHz CLOCK						
External Clock Frequency	CLK_SEL=5		19.2		MHz	
Sample Rate, Fast	DLPFCFG=0 SAMPLERATEDIV = 0		8		kHz	
Sample Rate, Slow	DLPFCFG=1,2,3,4,5, or 6 SAMPLERATEDIV = 0		1		kHz	
Reference Clock Output	CLKOUTEN = 1		1.024		MHz	
PLL Settling Time			1		ms	

Notes:

1. Tested in production
2. Based on characterization of 30 parts over temperature on evaluation board or in socket
3. Typical. Randomly selected part measured at room temperature on evaluation board or in socket

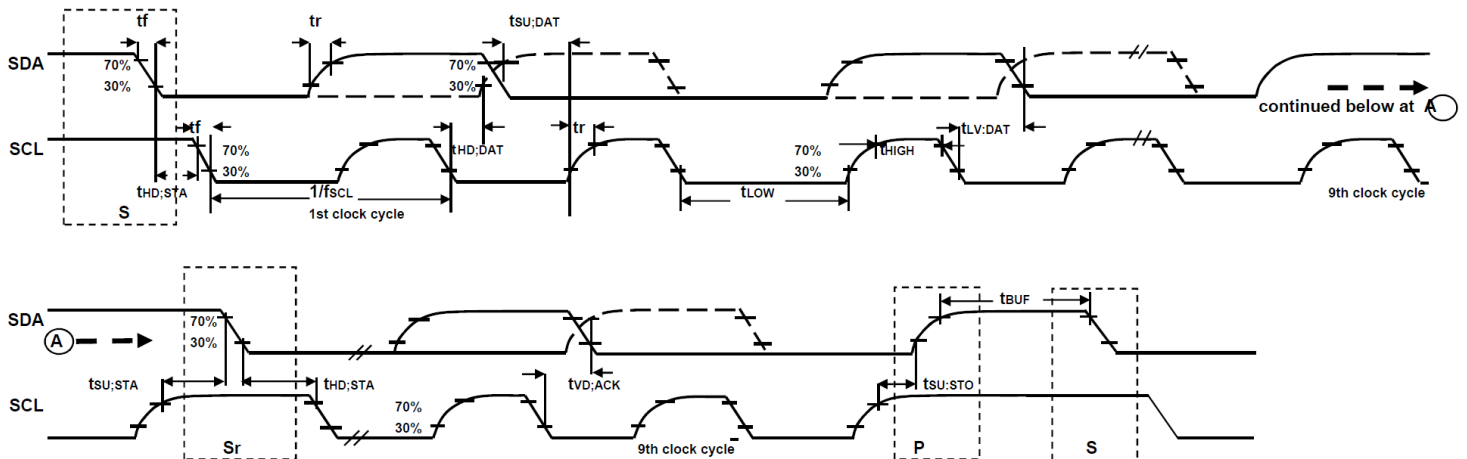
3.5 I²C Timing Characterization

Typical Operating Circuit of Section 4.2, VDD = 2.5V, VLOGIC = 1.8V±5% (MPU-3050 only), 2.5V±5%, 3.0V±5%, or 3.3V±5%, T_A=25°C.

Parameters	Conditions	Min	Typical	Max	Units	Notes
I²C TIMING						
f _{SCL} , SCL Clock Frequency	I ² C FAST-MODE C _b bus cap. from 10 to 400pF	0		400	kHz	1
t _{HD,STA} , (Repeated) START Condition Hold Time		0.6			μs	1
t _{LOW} , SCL Low Period		1.3			μs	1
t _{HIGH} , SCL High Period		0.6			μs	1
t _{SU,STA} , Repeated START Condition Setup Time		0.6			μs	1
t _{HD,DAT} , SDA Data Hold Time		0			μs	1
t _{SU,DAT} , SDA Data Setup Time		100			ns	1
t _r , SDA and SCL Rise Time		20+0.1 C _b		300	ns	1
t _f , SDA and SCL Fall Time		20+0.1 C _b		300	ns	1
t _{SU,STO} , STOP Condition Setup Time		0.6			μs	1
t _{BUF} , Bus Free Time Between STOP and START Condition		1.3			μs	1
C _b , Capacitive Load for each Bus Line			< 400		pF	
t _{VD,DAT} , Data Valid Time				0.9	μs	1
t _{VD,ACK} , Data Valid Acknowledge Time				0.9	μs	1

Notes:

- Based on characterization of 5 parts over temperature on evaluation board or in socket



I²C Bus Timing Diagram

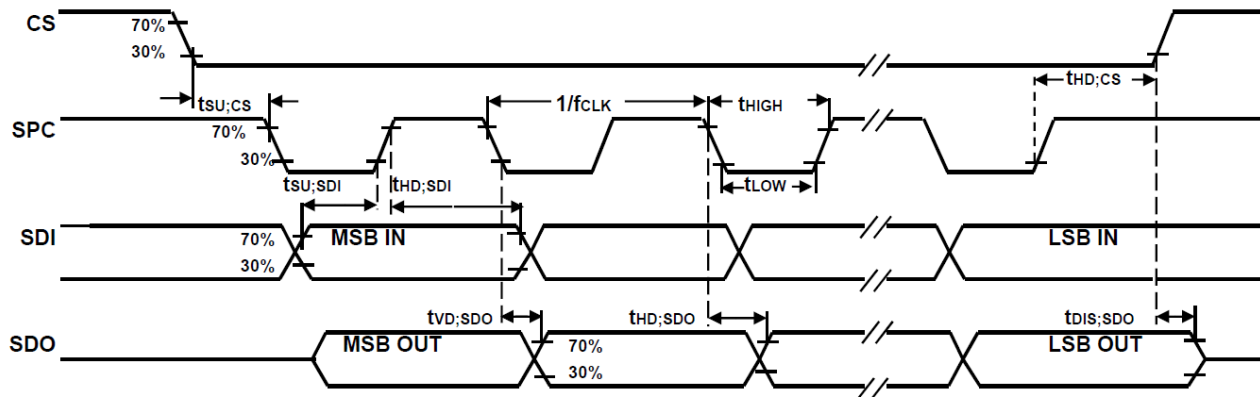
3.6 SPI Timing Characterization (MPU-3000 only)

Typical Operating Circuit of Section 4.2, VDD = 2.1V to 3.6V, T_A = -40°C to +85°C, unless otherwise noted. Typical values are at T_A=25°C.

Parameters	Conditions	Min	Typical	Max	Units
SPI TIMING					
f _{SCLK} , SCLK Clock Frequency		0.9		1	MHz
t _{LOW} , SCLK Low Period		400			ns
t _{HIGH} , SCLK High Period		400			ns
t _{SU,CS} , CS Setup Time		8			ns
t _{HD,CS} , CS Hold Time		500			ns
t _{SU,SDI} , SDI Setup Time		11			ns
t _{HD,SDI} , SDI Hold Time		7			ns
t _{VD,SDO} , SDO Valid Time	C _{load} = 20pF			100	ns
t _{HD,SDO} , SDO Hold Time	C _{load} = 20pF	4			ns
t _{DIS,SDO} , SDO Output Disable Time				10	ns

Note:

1. Based on characterization of 5 parts over temperature on evaluation board or in socket



SPI Bus Timing Diagram



3.7 Absolute Maximum Ratings

Stress above those listed as “Absolute Maximum Ratings” may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these conditions is not implied. Exposure to the absolute maximum ratings conditions for extended periods may affect device reliability.

Absolute Maximum Ratings

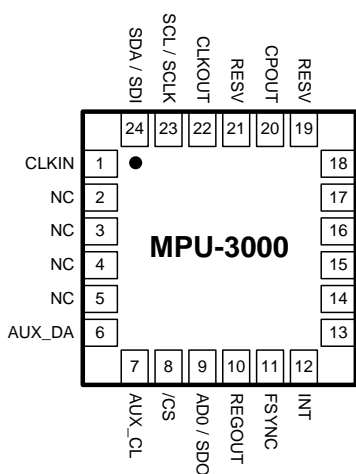
Parameter	Rating
Supply Voltage, VDD	-0.5V to +6V
VLOGIC Input Voltage Level (MPU-3050)	-0.5V to VDD + 0.5V
REGOUT	-0.5V to 2V
Input Voltage Level (CLKIN, AUX_DA, AD0, FSYNC, INT, SCL, SDA)	-0.5V to VDD + 0.5V
CPOUT (2.1V ≤ VDD ≤ 3.6V)	-0.5V to 30V
Acceleration (Any Axis, unpowered)	10,000g for 0.3ms
Operating Temperature Range	-40°C to +105°C
Storage Temperature Range	-40°C to +125°C
Electrostatic Discharge (ESD) Protection	1.5kV (HBM); 200V (MM)
Latch-up	60mA @ 125°C JEDEC Condition “B”



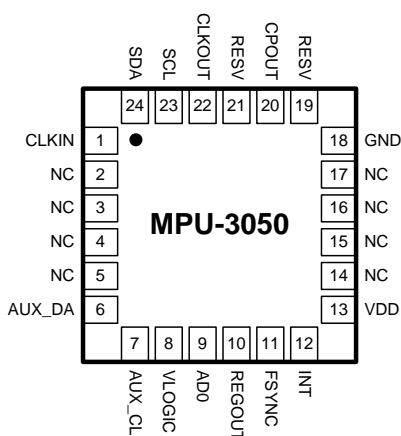
4 Applications Information

4.1 Pin Out and Signal Description

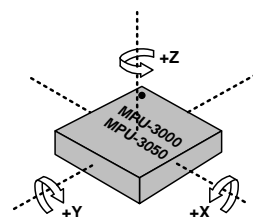
Pin Number	MPU-3000	MPU-3050	Pin Name	Pin Description
1	Y	Y	CLKIN	External reference clock input
6	Y	Y	AUX_DA	Interface to a 3 rd party accelerometer, SDA pin. Logic levels are set to be either VDD or VLOGIC. See Section 7 for more details.
7	Y	Y	AUX_CL	Interface to a 3 rd party accelerometer, SCL pin. Logic levels are set to be either VDD or VLOGIC. See Section 7 for more details.
8	Y		/CS	SPI chip select (0=SPI mode, 1= I ² C mode)
8		Y	VLOGIC	Digital I/O supply voltage. VLOGIC must be ≤ VDD at all times.
9	Y		AD0 / SDO	I ² C Slave Address LSB (AD0); SPI serial data output (SDO)
9		Y	AD0	I ² C Slave Address LSB
10	Y	Y	REGOUT	Regulator filter capacitor connection
11	Y	Y	FSYNC	Frame synchronization digital input
12	Y	Y	INT	Interrupt digital output (totem pole or open-drain)
13	Y	Y	VDD	Power supply voltage and Digital I/O supply voltage
18	Y	Y	GND	Power supply ground
19	Y	Y	RESV	Reserved. Do not connect.
20	Y	Y	CPOUT	Charge pump capacitor connection
21	Y	Y	RESV	Reserved. Do not connect.
22	Y	Y	CLKOUT	1MHz clock output for third-party accelerometer synchronization
23	Y		SCL / SCLK	I ² C serial clock (SCL); SPI serial clock (SCLK)
23		Y	SCL	I ² C serial clock
24	Y		SDA / SDI	I ² C serial data (SDA); SPI serial data input (SDI)
24		Y	SDA	I ² C serial data
2, 3, 4, 5, 14, 15, 16, 17	Y	Y	NC	Not internally connected. May be used for PCB trace routing.



QFN Package (Top View)
24-pin, 4mm x 4mm x 0.9mm

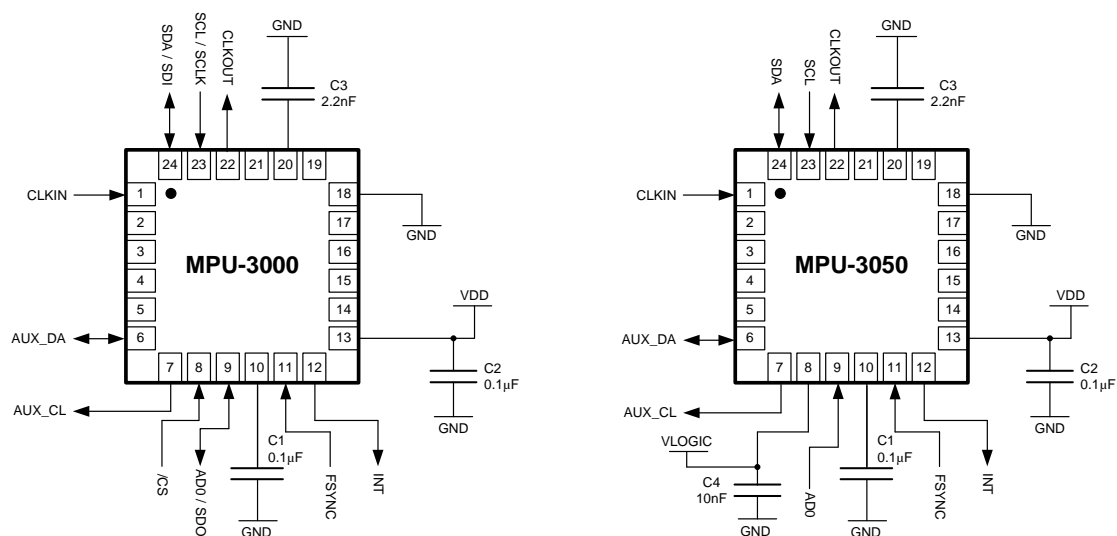


QFN Package (Top View)
24-pin, 4mm x 4mm x 0.9mm



**Orientation of Axes of Sensitivity
and Polarity of Rotation**

4.2 Typical Operating Circuits



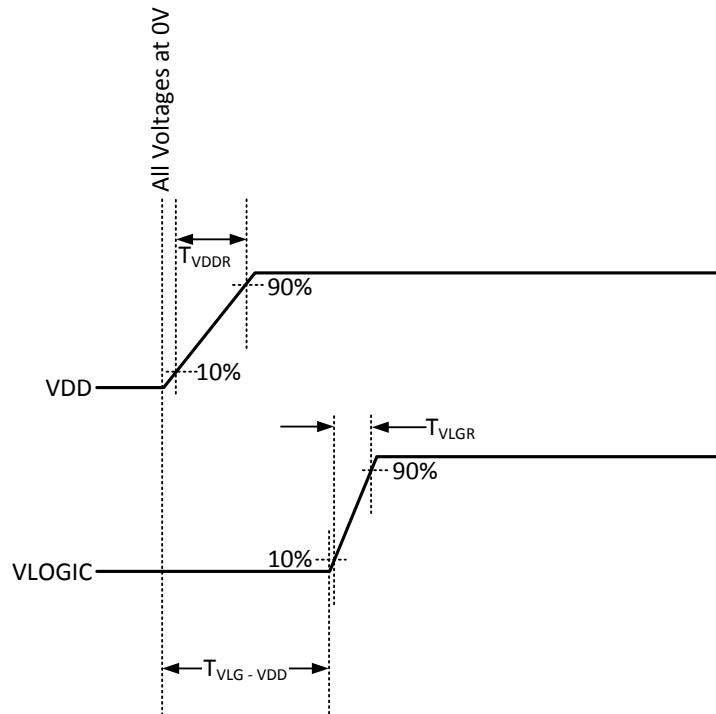
Typical Operating Circuits

4.3 Bill of Materials for External Components

Component	Label	Specification	Quantity
VDD Bypass Capacitor	C1	Ceramic, X7R, 0.1µF ±10%, 4V	1
Regulator Filter Capacitor	C2	Ceramic, X7R, 0.1µF ±10%, 2V	1
Charge Pump Capacitor	C3	Ceramic, X7R, 2.2nF ±10%, 50V	1
VLOGIC Bypass Capacitor	C4*	Ceramic, X7R, 10nF ±10%, 4V	1

*MPU-3050 only

4.4 Recommended Power-on Procedure

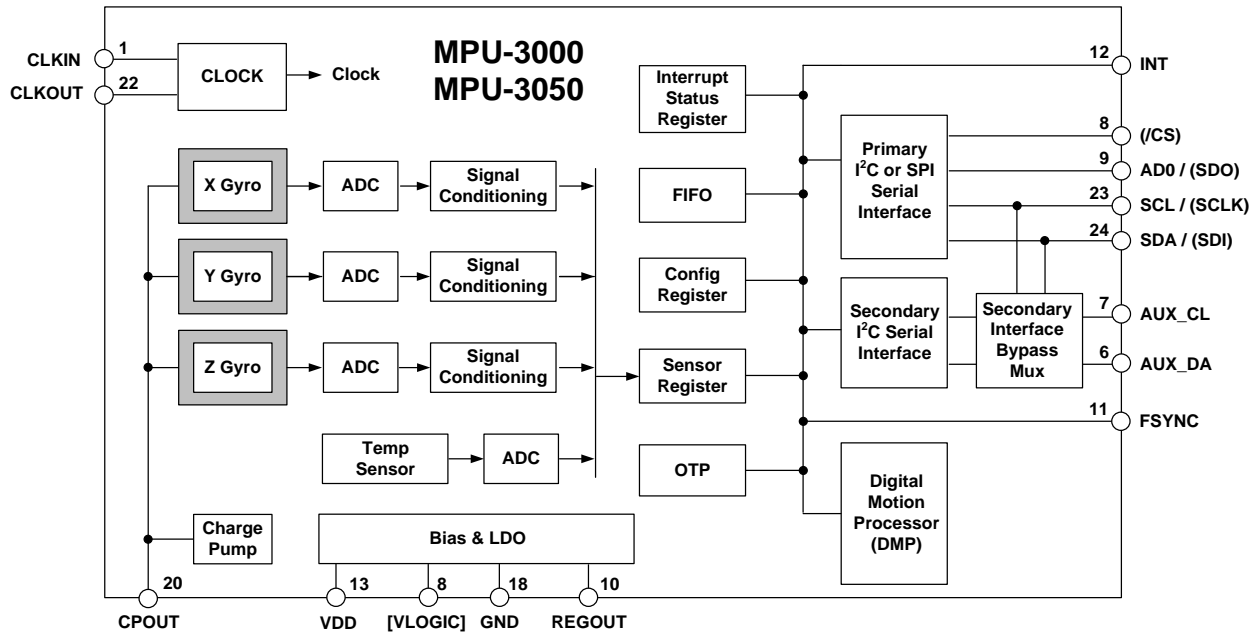


Power-Up Sequencing

1. T_{VDDR} is VDD rise time: Time for VDD to rise from 10% to 90% of its final value
2. T_{VDDR} is $\leq 10\text{msec}$
3. T_{VLGR} is VLOGIC rise time: Time for VLOGIC to rise from 10% to 90% of its final value
4. T_{VLGR} is $\leq 1\text{msec}$
5. $T_{VLG-VDD}$ is the delay from the start of VDD ramp to the start of VLOGIC rise
6. $T_{VLG-VDD}$ is 0 to 20msec but VLOGIC amplitude must always be \leq VDD amplitude
7. VDD and VLOGIC must be monotonic ramps

5 Functional Overview

5.1 Block Diagram



Note: Pin names in round brackets () are MPU-3000 only
Pin names in square brackets [] are MPU-3050 only

5.2 Overview

The MPU-30X0 is comprised of the following key blocks / functions:

- Three-axis MEMS rate gyroscope sensors with 16-bit ADCs and signal conditioning
- Digital Motion Processor (DMP)
- Primary I²C and SPI (MPU-3000 only) serial communications interfaces
- Secondary I²C serial interface for 3rd party accelerometer
- Clocking
- Sensor Data Registers
- FIFO
- Interrupts
- Digital-Output Temperature Sensor
- Bias and LDO
- Charge Pump

5.3 Three-Axis MEMS Gyroscope with 16-bit ADCs and Signal Conditioning

The MPU-30X0 consists of three independent vibratory MEMS rate gyroscopes, which detect rotation about the X, Y, and Z axes. When the gyros are rotated about any of the sense axes, the Coriolis Effect causes a vibration that is detected by a capacitive pickoff. The resulting signal is amplified, demodulated, and filtered to produce a voltage that is proportional to the angular rate. This voltage is digitized using individual on-chip 16-bit Analog-to-Digital Converters (ADCs) to sample each axis. The full-scale range of the gyro sensors may be digitally programmed to ± 250 , ± 500 , ± 1000 , or ± 2000 degrees per second (dps). ADC sample rate is programmable from 8,000 samples per second, down to 3.9 samples per second, and user-selectable low-pass filters enable a wide range of cut-off frequencies.



5.4 Digital Motion Processor

The embedded Digital Motion Processor (DMP) is located within the MPU-30X0 and offloads computation of motion processing algorithms from the host processor. The DMP acquires data from accelerometers, gyroscopes, and additional sensors such as magnetometers, and processes the data. The resulting data can be read from the DMP's registers, or can be buffered in a FIFO. The DMP has access to some of MPU's external pins, which can be used for synchronizing external devices to the motion sensors, or generating interrupts for the application.

The purpose of the DMP is to offload both timing requirements and processing power from the host processor. Typically, motion processing algorithms should be run at a high rate, often around 200Hz, in order to provide accurate results with low latency. This is required even if the application updates at a much lower rate; for example, a low power user interface may update as slowly as 5Hz, but the motion processing should still run at 200Hz. The DMP can be used as a tool in order to minimize power, simplify timing and software architecture, and save valuable MIPS on the host processor for use in the application.

5.5 Primary I²C and SPI Serial Communications Interfaces

The MPU-30X0 communicates to a system processor using either SPI (MPU-3000 only) or I²C serial interfaces, and the device always acts as a slave when communicating to the system processor. The logic level for communications to the master is set by the voltage on the VLOGIC pin (MPU-3050) or by VDD (MPU-3000). The LSB of the of the I²C slave address is set by pin 9 (AD0).

The selection of I²C versus SPI modes (MPU-3000 only) is described in more detail in Section 7. The LSB of the of the I²C slave address is set by pin 9.

5.6 Secondary I²C Serial Interface (for a third-party Accelerometer)

The MPU-30X0 has a secondary I²C bus for communicating to an off-chip 3-axis digital output accelerometer. This bus has two operating modes: I²C Master Mode, where the MPU-30X0 acts as a master to an external accelerometer connected to the secondary I²C bus; and Pass-Through Mode, where the MPU-30X0 directly connects the primary and secondary I²C buses together, to allow the system processor to directly communicate with the external accelerometer.

Secondary I²C Bus Modes of Operation:

- I²C Master Mode: allows the MPU-30X0 to directly access the data registers of an external digital accelerometer. In this mode, the MPU-30X0 directly obtains sensor data from accelerometers and optionally, another sensor (such as a magnetometer), thus allowing the on-chip DMP to generate sensor fusion data without intervention from the system applications processor. In I²C master mode, the MPU-30X0 can be configured to perform burst reads, returning the following data from the accelerometer:
 - X accelerometer data (2 bytes)
 - Y accelerometer data (2 bytes)
 - Z accelerometer data (2 bytes)
- Pass-Through Mode: allows an external system processor to act as master and directly communicate to the external accelerometer connected to the secondary I²C bus pins (AUX_DA and AUX_CL). This is useful for configuring the accelerometers, or for keeping the MPU-30X0 in a low-power mode, when only accelerometers are to be used. In this mode, the secondary I²C bus control logic (third-party accelerometer Interface block) of the MPU-30X0 is disabled, and the secondary I²C pins AUX_DA and AUX_CL (Pins 6 and 7) are connected to the main I²C bus (Pins 23 and 24) through analog switches.

Secondary I²C Bus IO Logic Levels

The logic levels of the secondary I²C bus can be programmed to be either VDD or VLOGIC (see Sections 7 and 8).



6 Clocking

6.1 Internal Clock Generation

The MPU-30X0 has a flexible clocking scheme, allowing for a variety of internal or external clock sources for the internal synchronous circuitry. This synchronous circuitry includes the signal conditioning and ADCs, the DMP, and various control circuits and registers. An on-chip PLL provides flexibility in the allowable inputs for generating this clock.

Allowable internal sources for generating the internal clock are:

- An internal relaxation oscillator
- Any of the X, Y, or Z gyros (MEMS oscillators with an accuracy of $\pm 2\%$ over temperature)

Allowable external clocking sources are:

- 32.768kHz square wave
- 19.2MHz square wave

Which source to select for generating the internal synchronous clock depends on the availability of external sources and the requirements for power consumption and clock accuracy. Most likely, these requirements will vary by mode of operation. For example, in one mode, where the biggest concern is power consumption, one may wish to operate the Digital Motion Processor of the MPU-30X0 to process accelerometer data, while keeping the gyros off. In this case, the internal relaxation oscillator is a good clock choice. However, in another mode, where the gyros are active, selecting the gyros as the clock source provides for a more-accurate clock source.

Clock accuracy is important, since timing errors directly affect the distance and angle calculations performed by the Digital Motion Processor (or by extension, by any processor).

There are also start-up conditions to consider. When the MPU-30X0 first starts up, the device operates off of its internal clock, until programmed to operate from another source. This allows the user, for example, to wait for the MEMS oscillators to stabilize before they are selected as the clock source.

6.2 Clock Output

In addition, the MPU-30X0 provides a clock output, which allows the device to operate synchronously with an external digital 3-axis accelerometer. Operating synchronously provides for higher-quality sensor fusion data, since the sampling instant for the sensor data can be set to be coincident for all sensors.

6.3 Sensor Data Registers

The sensor data registers contain the latest gyro and temperature data. They are read-only registers, and are accessed via the Serial Interface. Data from these registers may be read anytime, however, the interrupt function may be used to determine when new data is available.

6.4 FIFO

The MPU-30X0 contains a 512-byte FIFO register that is accessible via the Serial Interface. The FIFO configuration register determines what data goes into it, with possible choices being gyro data, accelerometer data, temperature readings, auxiliary ADC readings, and FSYNC input. A FIFO counter keeps track of how many bytes of valid data are contained in the FIFO. The FIFO register supports burst reads. The interrupt function may be used to determine when new data is available.

6.5 Interrupts

Interrupt functionality is configured via the Interrupt Configuration register. Items that are configurable include the INT pin configuration, the interrupt latching and clearing method, and triggers for the interrupt. Items that can trigger an interrupt are (1) Clock generator locked to new reference oscillator (used when switching clock sources); (2) Digital Motion Processor Done (programmable function); (3) new data is available to be read (from the FIFO and Data registers); and (4) the MPU-30X0 did not receive an acknowledge from the accelerometer on the Secondary I²C bus. The interrupt status can be read from the Interrupt Status register.

**6.6 Digital-Output Temperature Sensor**

An on-chip temperature sensor and ADC are used to measure the MPU-30X0 die temperature. The readings from the ADC can be read from the FIFO or the Sensor Data registers.

6.7 Bias and LDO

The bias and LDO section generates the internal supply and the reference voltages and currents required by the MPU-30X0. Its two inputs are an unregulated VDD of 2.1V to 3.6V and a VLOGIC logic reference supply voltage of 1.71V to VDD (MPU-3050 only). The LDO output is bypassed by a 0.1 μ F capacitor at REGOUT.

6.8 Charge Pump

An on-board charge pump generates the high voltage required for the MEMS oscillators. Its output is bypassed by a 2.2nF capacitor at CPOUT.

6.9 Chip Version

The chip version is written into OTP memory.



7 Digital Interface

7.1 I²C and SPI (MPU-3000 only) Serial Interfaces

The internal registers and memory of the MPU-3000/MPU-3050 can be accessed using either I²C or SPI (MPU-3000 only). SPI operates in four-wire mode.

Serial Interface

Pin Number	MPU-3000	MPU-3050	Pin Name	Pin Description
8	Y		/CS	SPI chip select (0=SPI mode, I ² C disable, 1= I ² C mode, SPI disable)
8		Y	VLOGIC	Digital I/O supply voltage. VLOGIC must be ≤ VDD at all times.
9	Y		AD0 / SDO	I ² C Slave Address LSB (AD0); SPI serial data output (SDO)
9		Y	AD0	I ² C Slave Address LSB
23	Y		SCL / SCLK	I ² C serial clock (SCL); SPI serial clock (SCLK)
23		Y	SCL	I ² C serial clock
24	Y		SDA / SDI	I ² C serial data (SDA); SPI serial data input (SDI)
24		Y	SDA	I ² C serial data

Note 1:

To prevent switching into I²C mode when using SPI (MPU-3000), the I²C interface should be disabled by setting the *I2C_IF_DIS* configuration bit in the *WHO_AM_I* register. Setting this bit should be performed immediately after waiting the time specified by the “Start-Up Time for Register Read/Write” in Section 3.2.

7.1.1 I²C Interface

I²C is a two-wire interface comprised of the signals serial data (SDA) and serial clock (SCL). In general, the lines are open-drain and bi-directional. In a generalized I²C interface implementation, attached devices can be a master or a slave. The master device puts the slave address on the bus, and the slave device with the matching address acknowledges the master.

The MPU-30X0 always operates as a slave device when communicating to the system processor, which thus acts as the master. SDA and SCL lines typically need pull-up resistors to VDD. The maximum bus speed is 400kHz.

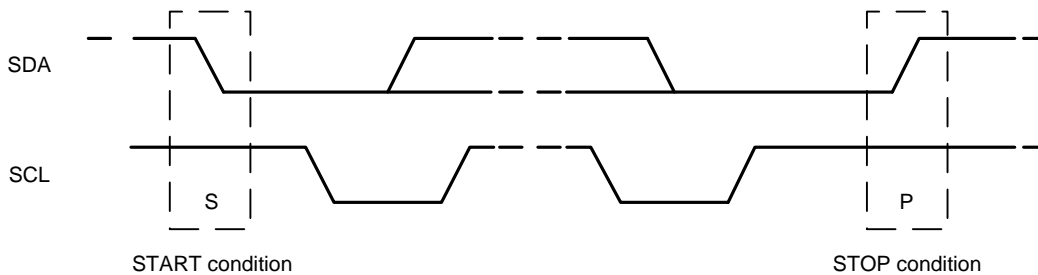
The slave address of the MPU-30X0 is b110100X which is 7 bits long. The LSB bit of the 7 bit address is determined by the logic level on pin AD0. This allows two MPU-30X0s to be connected to the same I²C bus. When used in this configuration, the address of the one of the devices should be b1101000 (pin AD0 is logic low) and the address of the other should be b1101001 (pin AD0 is logic high). The I²C address is stored in *WHO_AM_I* register.

I²C Communications Protocol

START (S) and STOP (P) Conditions

Communication on the I²C bus starts when the master puts the START condition (S) on the bus, which is defined as a HIGH-to-LOW transition of the SDA line while SCL line is HIGH (see figure below). The bus is considered to be busy until the master puts a STOP condition (P) on the bus, which is defined as a LOW to HIGH transition on the SDA line while SCL is HIGH (see figure below).

Additionally, the bus remains busy if a repeated START (Sr) is generated instead of a STOP condition.

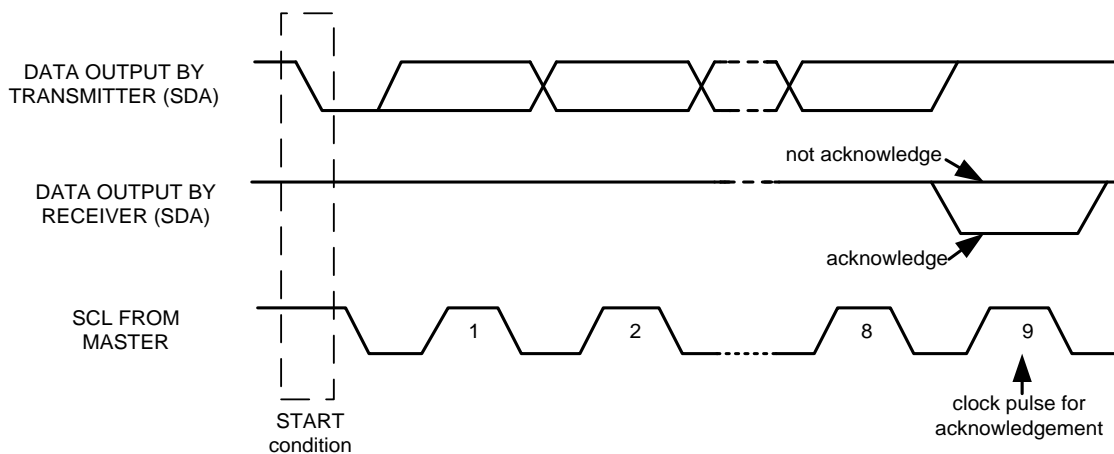


START and STOP Conditions

Data Format / Acknowledge

I²C data bytes are defined to be 8 bits long. There is no restriction to the number of bytes transmitted per data transfer. Each byte transferred must be followed by an acknowledge (ACK) signal. The clock for the acknowledge signal is generated by the master, while the receiver generates the actual acknowledge signal by pulling down SDA and holding it low during the HIGH portion of the acknowledge clock pulse.

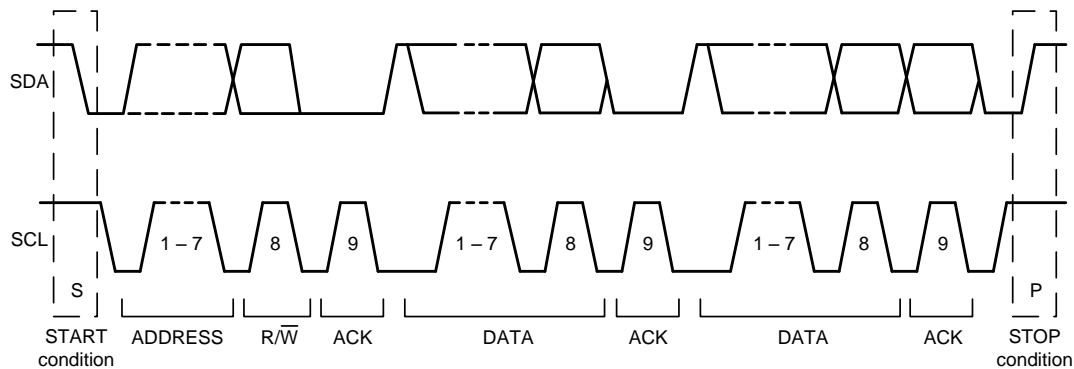
If a slave is busy and cannot transmit or receive another byte of data until some other task has been performed, it can hold SCL LOW, thus forcing the master into a wait state. Normal data transfer resumes when the slave is ready, and releases the clock line (refer to the following figure).



Acknowledge on the I²C Bus

Communications

After beginning communications with the START condition (S), the master sends a 7-bit slave address followed by an 8th bit, the read/write bit. The read/write bit indicates whether the master is receiving data from or is writing to the slave device. Then, the master releases the SDA line and waits for the acknowledge signal (ACK) from the slave device. Each byte transferred must be followed by an acknowledge bit. To acknowledge, the slave device pulls the SDA line LOW and keeps it LOW for the high period of the SCL line. Data transmission is always terminated by the master with a STOP condition (P), thus freeing the communications line. However, the master can generate a repeated START condition (Sr), and address another slave without first generating a STOP condition (P). A LOW to HIGH transition on the SDA line while SCL is HIGH defines the stop condition. All SDA changes should take place when SCL is low, with the exception of start and stop conditions.



Complete I²C Data Transfer

To write the internal MPU-30X0 registers, the master transmits the start condition (S), followed by the I²C address and the write bit (0). At the 9th clock cycle (when the clock is high), the MPU-30X0 acknowledges the transfer. Then the master puts the register address (RA) on the bus. After the MPU-30X0 acknowledges the reception of the register address, the master puts the register data onto the bus. This is followed by the ACK signal, and data transfer may be concluded by the stop condition (P). To write multiple bytes after the last ACK signal, the master can continue outputting data rather than transmitting a stop signal. In this case, the MPU-30X0 automatically increments the register address and loads the data to the appropriate register. The following figures show single and two-byte write sequences.

Single-Byte Write Sequence

Master	S	AD+W		RA		DATA		P
Slave			ACK		ACK		ACK	

Burst Write Sequence

Master	S	AD+W		RA		DATA		DATA		P
Slave			ACK		ACK		ACK		ACK	

To read the internal MPU-30X0 registers, the master sends a start condition, followed by the I²C address and a write bit, and then the register address that is going to be read. Upon receiving the ACK signal from the MPU-30X0, the master transmits a start signal followed by the slave address and read bit. As a result, the MPU-30X0 sends an ACK signal and the data. The communication ends with a not acknowledge (NACK) signal and a stop bit from master. The NACK condition is defined such that the SDA line remains high at the 9th clock cycle. The following figures show single and two-byte read sequences.

Single-Byte Read Sequence

Master	S	AD+W		RA		S	AD+R			NACK	P
Slave			ACK		ACK			ACK	DATA		

Burst Read Sequence

Master	S	AD+W		RA		S	AD+R			ACK		NACK	P
Slave			ACK		ACK			ACK	DATA		DATA		

**I²C Terms**

Signal	Description
S	Start Condition: SDA goes from high to low while SCL is high
AD	Slave I ² C address
W	Write bit (0)
R	Read bit (1)
ACK	Acknowledge: SDA line is low while the SCL line is high at the 9 th clock cycle
NACK	Not-Acknowledge: SDA line stays high at the 9 th clock cycle
RA	MPU-30X0 internal register address
DATA	Transmit or received data
P	Stop condition: SDA going from low to high while SCL is high

7.1.2 SPI interface (MPU-3000 only)

SPI is a 4-wire synchronous serial interface that uses two control and two data lines. The MPU-3000 always operates as a Slave device during standard Master-Slave SPI operation. With respect to the Master, the Serial Clock output (SCLK), the Data Output (SDO) and the Data Input (SDI) are shared among the Slave devices. The Master generates an independent Chip Select (/CS) for each Slave device; /CS goes low at the start of transmission and goes back high at the end. The Serial Data Output (SDO) line, remains in a high-impedance (high-z) state when the device is not selected, so it does not interfere with any active devices.

SPI Operational Features

1. Data is delivered MSB first and LSB last
2. Data is latched on rising edge of SCLK
3. Data should be transitioned on the falling edge of SCLK
4. SCLK frequency is 1MHz max
5. SPI read and write operations are completed in 16 or more clock cycles (two or more bytes). The first byte contains the SPI Address, and the following byte(s) contain(s) the SPI data. The first bit of the first byte contains the Read/Write bit and indicates the Read (1) or Write (0) operation. The following 7 bits contain the Register Address. In cases of multiple-byte Read/Writes, data is two or more bytes:

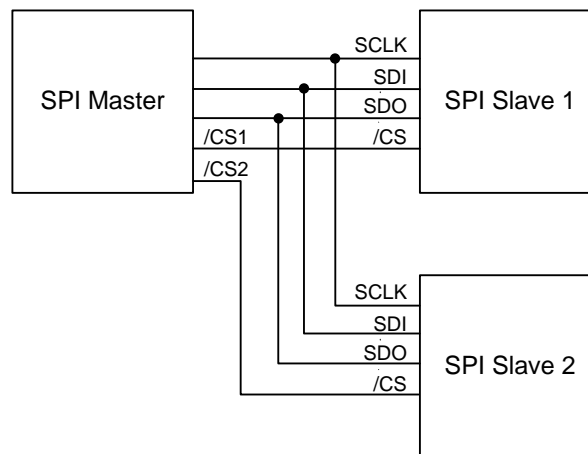
SPI Address format

MSB							LSB
R/W	A6	A5	A4	A3	A2	A1	A0

SPI Data format

MSB							LSB
D7	D6	D5	D4	D3	D2	D1	D0

6. Supports Single or Burst Read/Writes.



Typical SPI Master / Slave Configuration

Each SPI slave requires its own Chip Select (/CS) line. SDO, SDI and SCLK lines are shared. Only one /CS line is active (low) at a time ensuring that only one slave is selected at a time. The /CS lines of other slaves are held high which causes their respective SDO pins to be high-Z.



8 Serial Interface Considerations (MPU-3050)

8.1 MPU-3050 Supported Interfaces

The MPU-3050 supports I²C communications on both its primary (microprocessor) serial interface and its secondary (accelerometer) interface.

8.2 Logic Levels

The MPU-3050 I/O logic levels are set to be either VDD or VLOGIC, as shown in the table below.

I/O Logic Levels vs. *AUX_VDDIO* (Secondary I²C Bus IO Level)

<i>AUX_VDDIO</i>	MICROPROCESSOR LOGIC LEVELS (Pins: SDA, SCL, AD0, CLKIN, INT)	ACCELEROMETER LOGIC LEVELS (Pins: AUX_DA, AUX_CL)
0	VLOGIC	VLOGIC
1	VLOGIC	VDD

Notes:

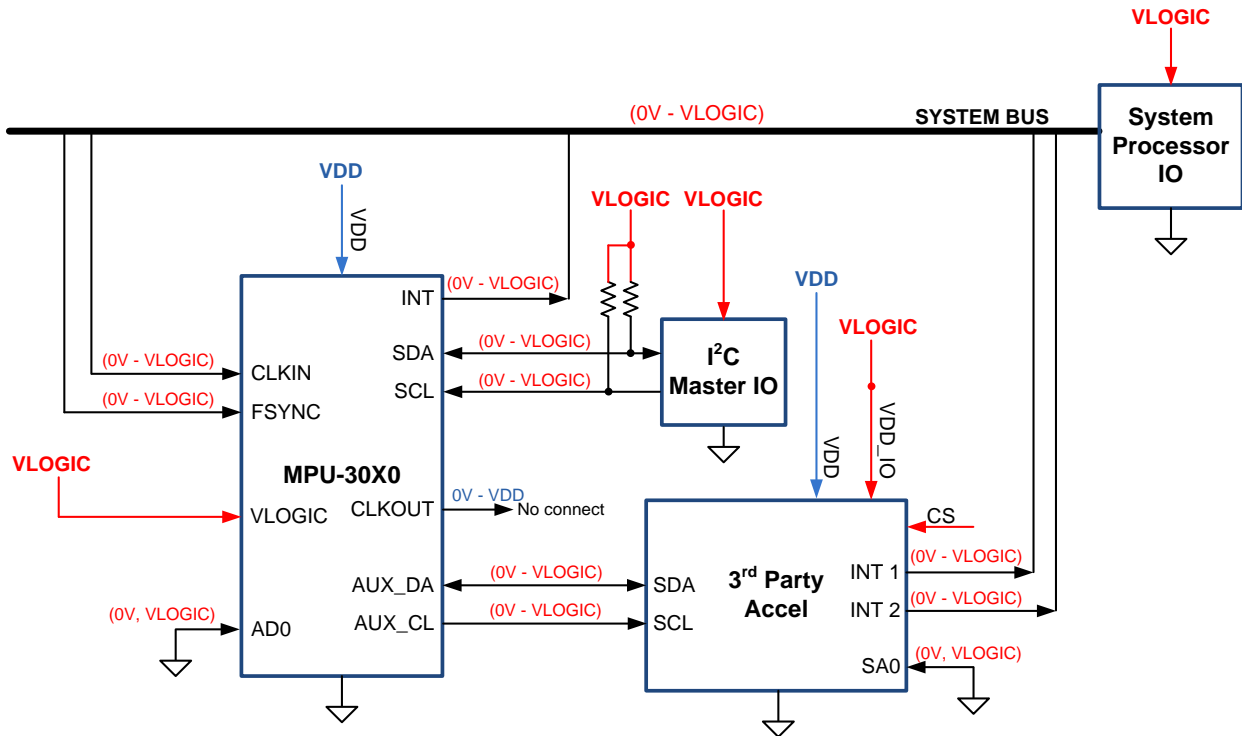
1. CLKOUT has logic levels that are always referenced to VDD
2. The power-on-reset value for *AUX_VDDIO* is 0.

VLOGIC may be set to be equal to VDD or to another voltage, such that at all times VLOGIC is \leq VDD. When *AUX_VDDIO* is set to 0 (its power-on-reset value), VLOGIC is the power supply voltage for both the microprocessor system bus and the accelerometer secondary bus, as shown in the figure of Section 8.2.1.

When *AUX_VDDIO* is set to 1, VLOGIC is the power supply voltage for the microprocessor system bus and VDD is the supply for the accelerometer secondary bus, as shown in the figure of Section 8.2.2.

8.2.1 AUX_VDDIO = 0

The figure below shows logic levels and voltage connections for AUX_VDDIO = 0. Note: Actual configuration will depend on the type of third-party accelerometer used.



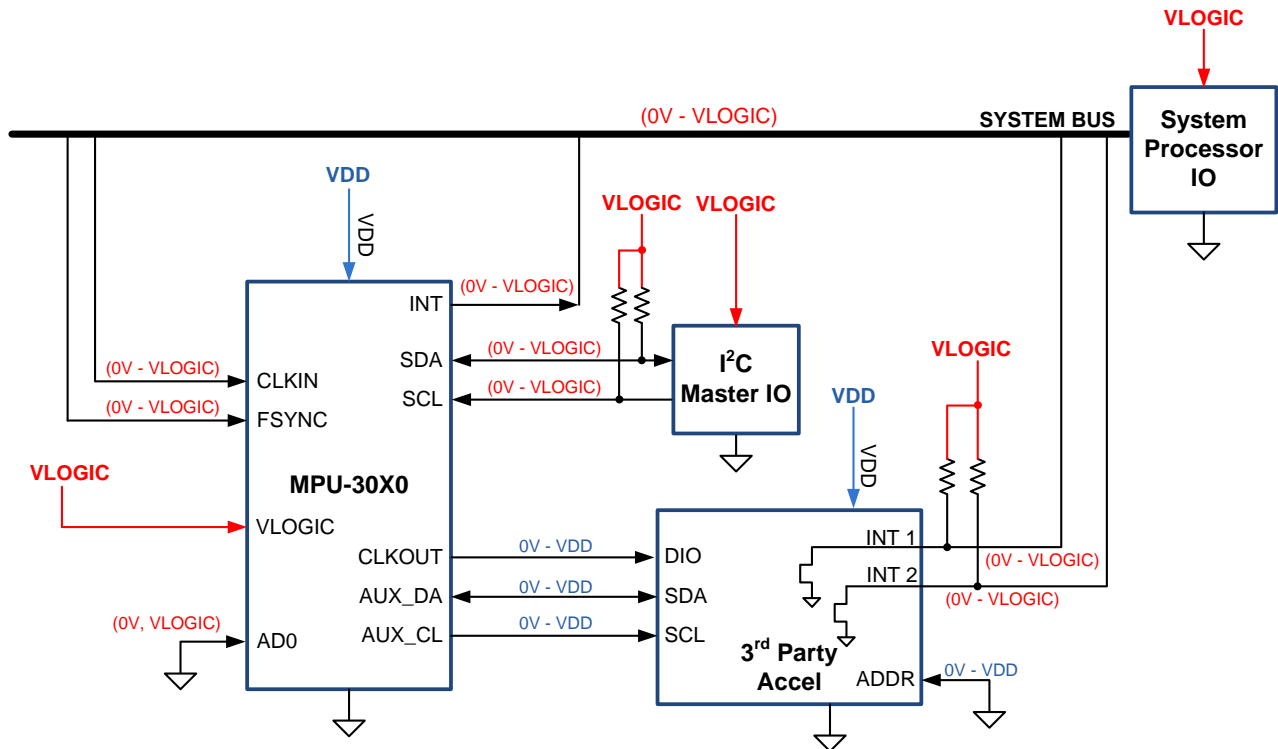
Notes:

1. AUX_VDDIO is bit 7 in Register 24, and determines the IO voltage levels of AUX_DA and AUX_CL (0 = set output levels relative to VLOGIC)
2. CLKOUT is always referenced to VDD
3. Other MPU-3050 logic IO are always referenced to VLOGIC

I/O Levels and Connections for AUX_VDDIO = 0

8.2.2 AUX_VDDIO = 1

When *AUX_VDDIO* is set to 1 by the user, VLOGIC is the power supply voltage for the microprocessor system bus and VDD is the power supply for the accelerometer secondary bus, as shown in the figure below. This is useful when interfacing to a third-party accelerometer where there is only one supply for both the logic and analog sections of the 3rd party accelerometer.



Voltage/ Configuration	Configuration 1	Configuration 2
VLOGIC	1.8V±5%	3.0V±5%
VDD	2.5V±5%	3.0V±5%
AUX_VDDIO	1	1

Notes:

- AUX_VDDIO is bit 7 in Register 24, and determines the IO voltage levels of AUX_DA and AUX_CL (1 = set output levels relative to VDD)
- CLKOUT is always referenced to VDD
- Other MPU-3050 logic IO are always referenced to VLOGIC
- Third-party accelerometer logic levels are referenced to VDD; setting INT1 and INT2 to open-drain configuration provides voltage compatibility when VDD ≠ VLOGIC.
When VDD = VLOGIC, INT1 and INT2 may be set to push-pull outputs, and the external pull-up resistors will not be needed.

I/O Levels and Connections for Two Example Power Configurations (*AUX_VDDIO* = 1)

Note: Actual configuration will depend on the type of third-party accelerometer used.

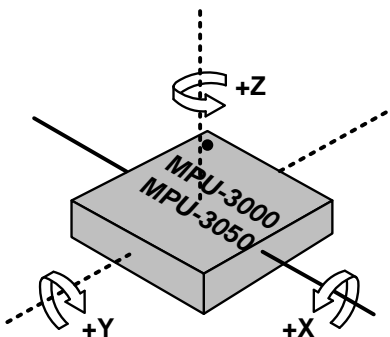
9 Assembly

This section provides general guidelines for assembling InvenSense Micro Electro-Mechanical Systems (MEMS) gyros packaged in Quad Flat No leads package (QFN) surface mount integrated circuits. The following six best practices will ensure higher quality in assembly.

1. Do not leave parts out of the original moisture-sealed bags for more than 48 hours before assembly
2. Do not solder the center pad
3. Do not place large insertion components, such as buttons, switches, connectors, or shielding boxes at a distance of less than 6 mm from the MEMS gyro
4. Do use Electrostatic Discharge (ESD) protection at or better than 200V, preferably 150V, to prevent Machine Model (MM) type ESD damage
5. Do use ESD protection measures to ensure that personnel prevent Human Body Model (HBM) type ESD damage
6. Do not mechanically impact or shock the package in any of the production processes

9.1 Orientation

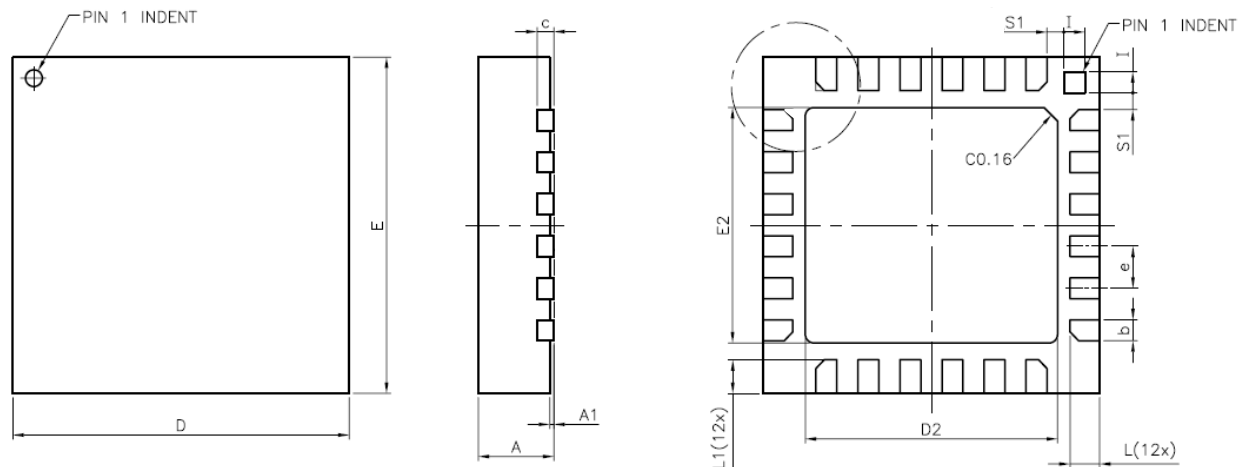
The diagram below shows the orientation of the axes of sensitivity and the polarity of rotation.



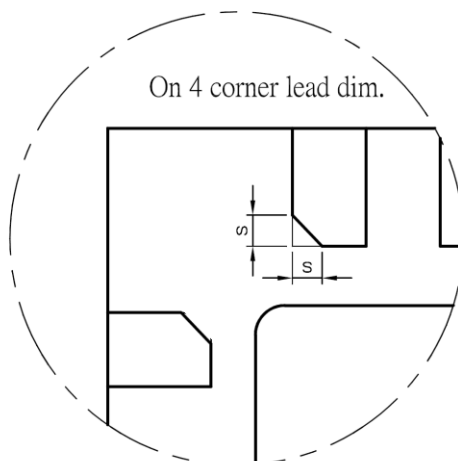
Orientation of Axes of Sensitivity and Polarity of Rotation

9.2 PCB Layout Guidelines

9.2.1 Package Dimensions



NOTE:
1. THE TERMINAL #1 IDENTIFIER
IS A LASER MARKED FEATURE



SYMBOLS	DIMENSIONS IN MILLIMETERS		
	MIN	NOM	MAX
A	0.85	0.90	0.95
A1	0.00	0.02	0.05
b	0.18	0.25	0.30
c	—	0.20 REF.	—
D	3.90	4.00	4.10
D2	2.95	3.00	3.05
E	3.90	4.00	4.10
E2	2.75	2.80	2.85
e	—	0.50	—
L	0.30	0.35	0.40
L1	0.35	0.40	0.45
I	0.20	0.25	0.30
s	0.05	—	0.15
S1	0.15	0.20	0.25

9.2.2 PCB Design Guidelines:

The Pad Diagram is shown in Figure 2 using a JEDEC type extension with solder rising on the outer edge. The Pad Dimensions Table shows pad sizing (mean dimensions) for the MPU-3050 product.

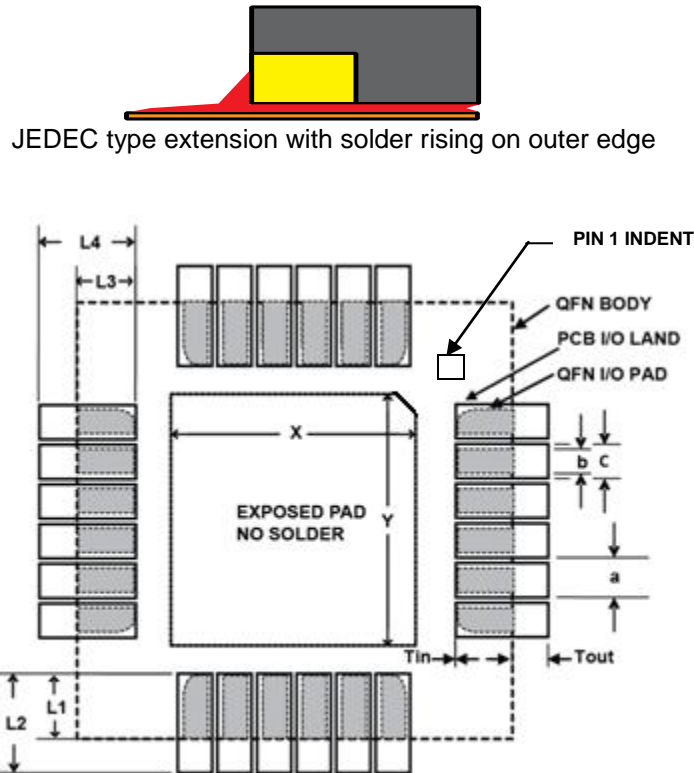


Figure 2: Pad Diagram

Nominal Package I/O Pad Dimensions (mm)	
Pad Pitch (a)	0.50
Pad Width (b)	0.30
Pad Length (L1)	0.40
Pad Length (L3)	0.35
Exposed Pad Width (X)	2.80
Exposed Pad Length (Y)	3.00
I/O Land Design Dimensions Guidelines (mm)	
Land Width (c)	0.35
Outward Extension (Tout)	0.40
Inward Extension (Tin)	0.05
Land Length (L2)	0.80
Land Length (L4)	0.75

Pad Dimensions Table (for Figure 2)

InvenSense MEMS Gyros sense rate of rotation. In addition, gyroscopes sense mechanical stress coming from the PCB. This PCB stress is minimized with simple design rules:



1. Component Placement – Testing indicates that there are no specific design considerations other than generally accepted industry design practices for component placement near the MPU-30X0 gyroscope to prevent noise coupling and thermo-mechanical stress.
2. The area below the MEMS gyro (on the same side of the board) must be defined as a keep-out area. It is strongly recommended to not place any structure in top metal layer underneath the keep-out area.
3. Traces connected to pads should be as much symmetric as possible. Symmetry and balance for pad connection will help component self alignment and will lead to better control of solder paste reduction after reflow.
4. Testing indicates that 3-Volt peak-to-peak signals run under the gyro package or directly on top of the package of frequencies from DC to 1MHz do not affect the operation of the MEMS gyro. However, routing traces or vias under the MEMS gyro package such that they run under the exposed die pad is prohibited.
5. To achieve best performance over temperature and to prevent thermo-mechanical package stress, do not place large insertion components like buttons, connectors, or shielding boxes at a distance of less than 6 mm from the MEMS gyro.

9.2.3 Exposed Die Pad Precautions

The MPU-30X0 has very low active and standby current consumption. The exposed die pad is not required for heat sinking, and should not be soldered to the PCB since soldering to it contributes to performance changes due to package thermo-mechanical stress. There is no electrical connection between the pad and the CMOS.

9.2.4 Gyro Removal from PCB

Never apply high mechanical force while removing MEMS gyros from PCB. Otherwise, the QFN package leads can be removed and failure analysis of the gyro unit will be impossible. Tweezers are practical. Do not apply a pulling force upward. Instead apply a gentle force sideward while heating. When sufficient heat has been applied, the unit will start to slide sideways and can now be pulled gently upwards with the tweezers.

In any case, mechanical or thermo-mechanical overstress during manual handling and soldering, (especially contact between the soldering iron or hot air gun and the package) has to be avoided.

If safe removal of the suspected component is not possible or deemed too risky, send the whole PCB or the part of the PCB containing the defective component back to InvenSense. If requested, we will return the PCB after we have removed the gyro.

9.3 Trace Routing

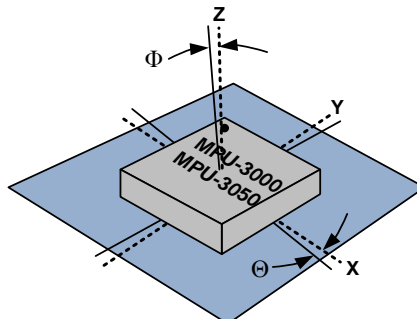
Testing indicates that 3-Volt peak-to-peak signals run under the gyro package or directly on top of the package of frequencies from DC to 1MHz do not affect the operation of the MEMS gyro. However, routing traces or vias under the MEMS gyro package such that they run under the exposed die pad is prohibited.

9.4 Component Placement

Do not place large insertion components such as keyboard or similar buttons, connectors, or shielding boxes at a distance of less than 6 mm from the MEMS gyro. Maintain generally accepted industry design practices for component placement near the MPU-3050 to prevent noise coupling and thermo-mechanical stress.

9.5 PCB Mounting and Cross-Axis Sensitivity

Orientation errors of the gyroscope mounted to the printed circuit board can cause cross-axis sensitivity in which one gyro responds to rotation about another axis, for example, the X-axis gyroscope responding to rotation about the Y or Z axes. The orientation mounting errors are illustrated in the figure below.



Package Gyro Axes (.....) Relative to PCB Axes (—) with Orientation Errors (Θ and Φ)

The table below shows the cross-axis sensitivity as a percentage of the specified gyroscope's sensitivity for a given orientation error.

Cross-Axis Sensitivity vs. Orientation Error

Orientation Error (θ or Φ)	Cross-Axis Sensitivity ($\sin\theta$ or $\sin\Phi$)
0°	0%
0.5°	0.87%
1°	1.75%

The specification for cross-axis sensitivity in Section 3 includes the effect of the die orientation error with respect to the package.



9.6 MEMS Handling Instructions

MEMS (Micro Electro-Mechanical Systems) are a time-proven, robust technology used in hundreds of millions of consumer, automotive and industrial products. MEMS devices consist of microscopic moving mechanical structures. They differ from conventional IC products even though they can be found in similar packages. Therefore, MEMS devices require different handling precautions than conventional ICs prior to mounting onto printed circuit boards (PCBs).

The MPU-30X0 gyroscope has a shock tolerance of 10,000g. InvenSense packages its gyroscopes as it deems proper for protection against normal handling and shipping. It recommends the following handling precautions to prevent potential damage.

- Individually packaged or trays of gyroscopes should not be dropped onto hard surfaces. Components placed in trays could be subject to *g*-forces in excess of 10,000g if dropped.
- Printed circuit boards that incorporate mounted gyroscopes should not be separated by manually snapping apart. This could also create *g*-forces in excess of 10,000g.

9.7 ESD Considerations

Establish and use ESD-safe handling precautions when unpacking and handling ESD-sensitive devices.

- The Tape-and-Reel moisture-sealed bag is an ESD approved barrier. The best practice is to keep the units in the original moisture sealed bags until ready for assembly.
- Restrict all device handling to ESD protected work areas that measure less than 200V static charge, or better, to less than 150V. Ensure that all workstations are properly grounded.
- Store ESD sensitive devices in ESD safe containers until ready for use.
- Ensure that personnel are properly grounded to prevent ESD.

9.8 Gyroscope Surface Mount Guidelines

Any material used in the surface mount assembly process of the MEMS gyroscope should be free of restricted RoHS elements or compounds. Pb-free solders should be used for assembly.

In order to assure gyroscope performance, several industry standard guidelines need to be considered for surface mounting. These guidelines are for both printed circuit board (PCB) design and surface mount assembly and are available from packaging and assembly houses.

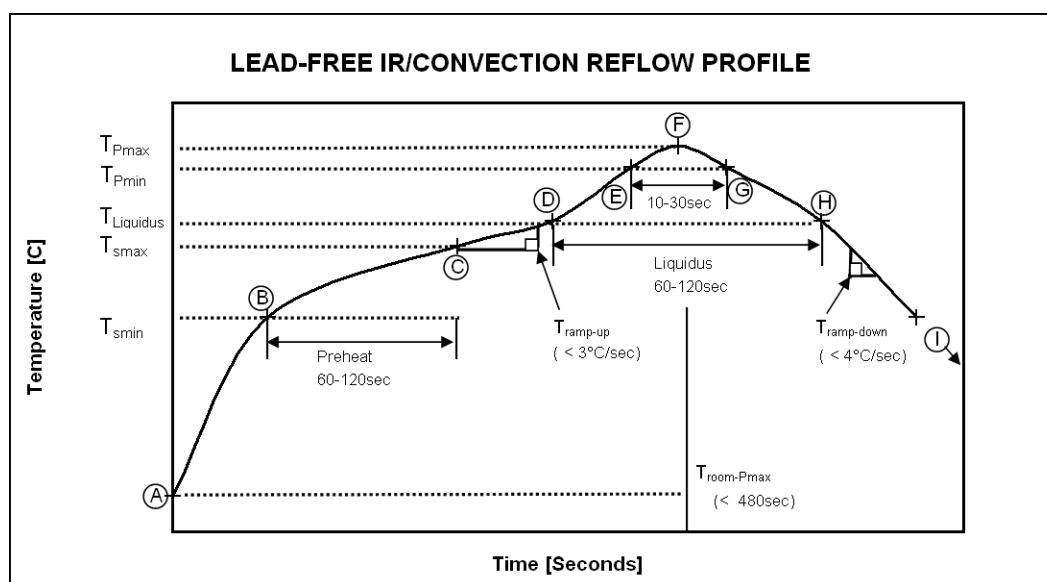
When using MEMS gyroscope components in plastic packages, package stress due to PCB mounting and assembly could affect the output offset and its value over a wide range of temperatures. This is caused by the mismatch between the Coefficient of Linear Thermal Expansion (CTE) of the package material and the PCB. Care must be taken to avoid package stress due to mounting.

9.9 Reflow Specification

The MPU-30X0 gyroscope was qualified in accordance with IPC/JEDEC J-STD-020D.01. This standard classifies proper packaging, storage and handling to avoid subsequent thermal and mechanical damage during assembly solder reflow attachment. Classification specifies a bake cycle, moisture soak cycle in a temperature humidity oven, followed by three solder reflow cycles and functional testing for qualification. All temperatures refer to the topside of the QFN package, as measured on the package body surface. The peak solder reflow classification temperature requirement is $(260 \pm 5/0^{\circ}\text{C})$ for lead-free soldering of components less than 1.6 mm thick.

Lower Production solder-reflow temperatures are recommended to use. Check the recommendations of your solder manufacturer. For optimum results, production solder reflow processes should use lower temperatures, reducing exposure to high temperatures, and using lower ramp-up and ramp-down rates than those listed in the qualification profile shown below.

Production reflow should never exceed the maximum constraints listed in the table and figure below for the qualification profile, as these represent the maximum tolerable ratings for the device.



Maximum Temperature IR / Convection Solder Reflow Curve Used for Qualification

Temperature Set Points for IR / Convection Reflow Corresponding to Figure Above

Step	Setting	CONSTRAINTS		
		Temp ($^{\circ}\text{C}$)	Time (sec)	Rate ($^{\circ}\text{C}/\text{sec}$)
A	Troom	25		
B	T _{Smin}	150		
C	T _{Smax}	200	$60 < t_{BC} < 120$	
D	T _{Liquidus}	217		$r(T_{\text{Liquidus}} - T_{\text{Pmax}}) < 3$
E	T _{Pmin} [255 $^{\circ}\text{C}$, 260 $^{\circ}\text{C}$]	255		$r(T_{\text{Liquidus}} - T_{\text{Pmax}}) < 3$
F	T _{Pmax} [260 $^{\circ}\text{C}$, 265 $^{\circ}\text{C}$]	260	$t_{AF} < 480$	$r(T_{\text{Liquidus}} - T_{\text{Pmax}}) < 3$
G	T _{Pmin} [255 $^{\circ}\text{C}$, 260 $^{\circ}\text{C}$]	255	$10 < t_{EG} < 30$	$r(T_{\text{Pmax}} - T_{\text{Liquidus}}) < 4$
H	T _{Liquidus}	217	$60 < t_{DH} < 120$	
I	T _{room}	25		

Note: For users T_{Pmax} must not exceed the Classification temperature (260 $^{\circ}\text{C}$). For suppliers T_{Pmax} must equal or exceed the Classification temperature.



MPU-3000/MPU-3050 Product Specification

Document Number: PS-MPU-3000A-00

Revision: 2.5

Release Date: 12/23/2010

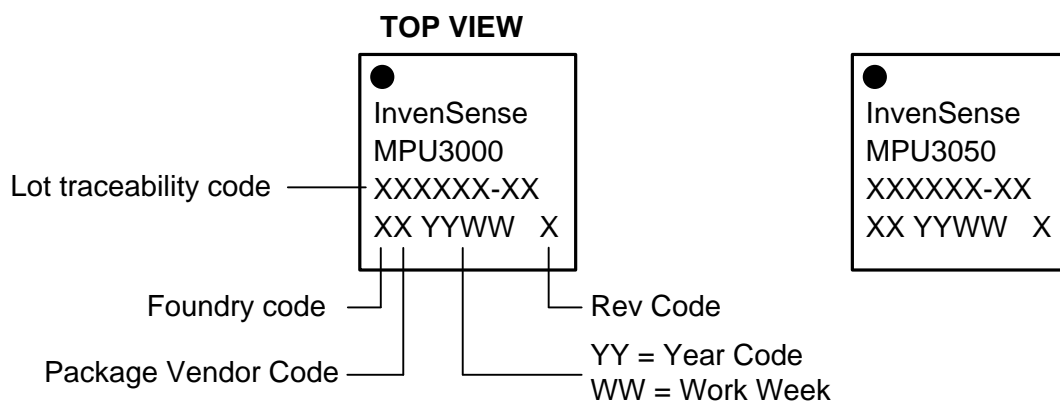
9.10 Storage Specifications

The storage specification of the MPU-30X0 gyroscope conforms to IPC/JEDEC J-STD-020C Moisture Sensitivity Level (MSL) 3.

Storage Specifications for MPU-30X0

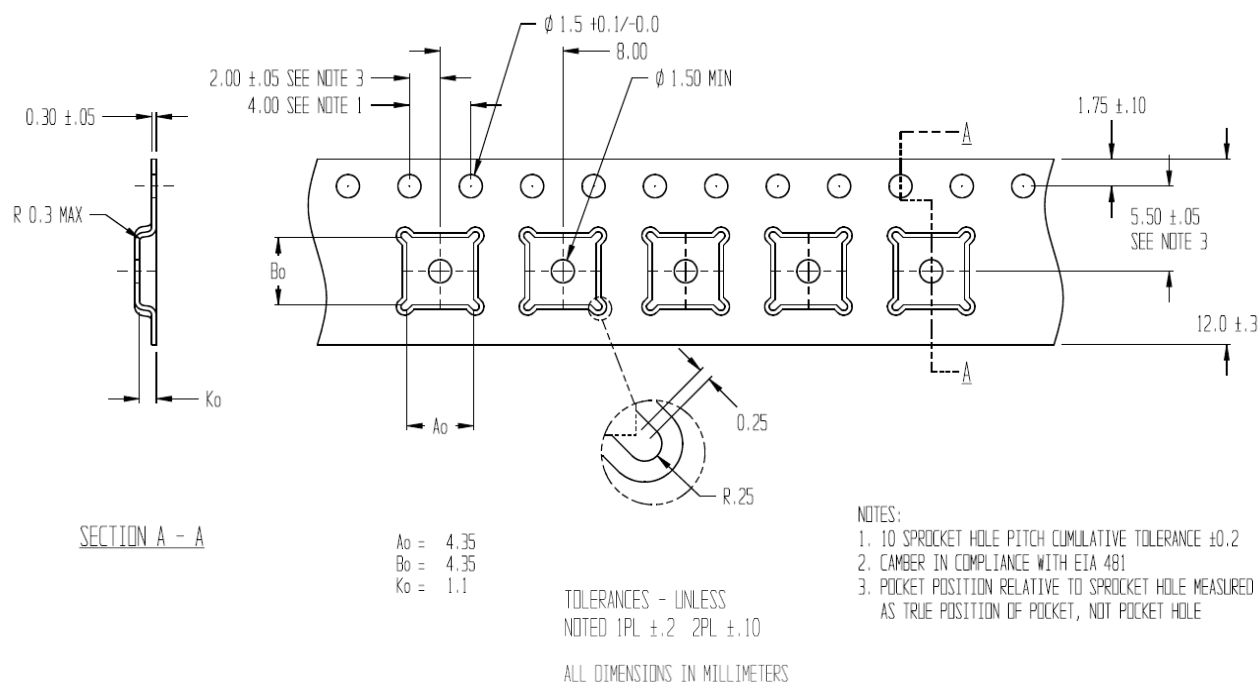
Calculated shelf-life in moisture-sealed bag	12 months -- Storage conditions: <40°C and <90% RH
After opening moisture-sealed bag	168 hrs -- Storage conditions: ambient ≤30°C at 60% RH

9.11 Package Marking Specification

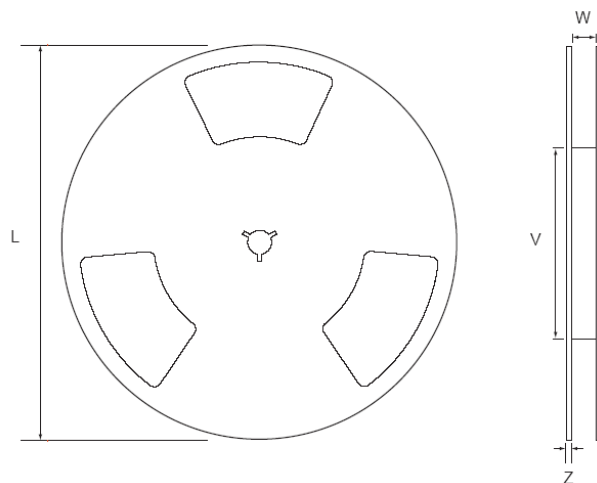


Package Marking Specification

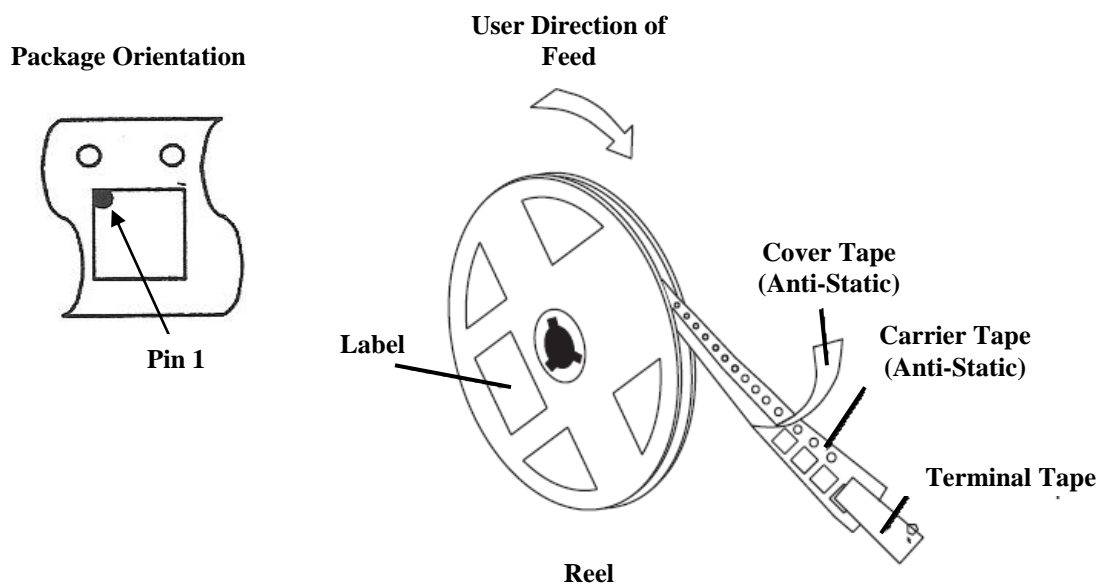
9.12 Tape & Reel Specification



Tape Dimensions


Reel Outline Drawing
Reel Dimensions and Package Size

PACKAGE SIZE	REEL (mm)			
	L	V	W	Z
4x4	330	100	13.2	2.2


Tape and Reel Specification
Reel Specifications

Quantity Per Reel	5,000
Reels per Box	1
Boxes Per Carton (max)	3
Pieces per Carton (max)	15,000



MPU-3000/MPU-3050 Product Specification

Document Number: PS-MPU-3000A-00

Revision: 2.5

Release Date: 12/23/2010

9.13 Label

InvenSense			
DEVICE (1P): MPU-3000A P.O:		REEL QTY (Q): 1000	
LOT 1 (IT): 123456	D/C (D): 0915	QTY (Q): 1000	
LOT 2 (IT):	D/C (D):	QTY (Q):	
Reel Date: 14/04/09		QC STAMP	



Location of Label

9.14 Packaging



Moisture Barrier Bag
With Labels

- Anti-static Label
- Moisture-Sensitive
Caution Label
- Tape & Reel Label

	Caution	LEVEL
	This bag contains MOISTURE-SENSITIVE DEVICES	If blank, see adjacent bar code label
1. Calculated shelf life in sealed bag: 12 months at <40°C and <90% relative humidity (RH) 2. Peak package body temperature: _____ °C If blank, see adjacent bar code label 3. After bag is opened, devices that will be subjected to reflow solder or other high temperature process must a) Mounted within: _____ hours of factory conditions If blank, see adjacent bar code label <30°C/80% RH, OR b) Stored at <10% RH 4. Devices require bake, before mounting, if: a) Humidity Indicator Card is >10% when read at 23 ± 5°C b) 3a or 3b not met 5. If baking is required, devices may be baked for 48 hours at 125 ± 5°C Note: If device containers cannot be subjected to high temperature or shorter bake times are desired, reference IPC/JEDEC J-STD-033 for bake procedure Bag Seal Date: _____ If blank, see adjacent bar code label Note: Level and body temperature defined by IPC/JEDEC J-STD-033		

Moisture-Sensitive Caution Label



Reel in Box



Box with Tape & Reel Label



10 Reliability

10.1 Qualification Test Policy

InvenSense's products complete a Qualification Test Plan before being released to production. The Qualification Test Plan for the MPU-30X0 followed the JEDEC 47G.01 Standards, "Stress-Test-Driven Qualification of Integrated Circuits," with the individual tests described below.

10.2 Qualification Test Plan

Accelerated Life Tests

TEST	Method/Condition	Lot Quantity	Sample / Lot	Acc / Reject Criteria
High Temperature Operating Life (HTOL/LFR)	JEDEC JESD22-A108C, Dynamic, 3.63V biased, T _j >125°C [read-points 168, 500, 1000 hours]	3	77	(0/1)
Steady-State Temperature Humidity Bias Life ⁽¹⁾	JEDEC JESD22-A101C, 85°C/85%RH [read-points 168, 500 hours], Information Only 1000 hours]	3	77	(0/1)
High Temperature Storage Life	JEDEC JESD22-A103C, Cond. A, 125°C Non-Bias Bake [read-points 168, 500, 1000 hours]	3	77	(0/1)

Device Component Level Tests

TEST	Method/Condition	Lot Quantity	Sample / Lot	Acc / Reject Criteria
ESD-HBM	JEDEC JESD22-A114F, Class 2 (1.5KV)	1	3	(0/1)
ESD-MM	JEDEC JESD22-A115-A, Class B (200V)	1	3	(0/1)
Latch Up	JEDEC JESD78B Level 2, 125C, +/- 60mA	1	6	(0/1)
Mechanical Shock	JEDEC JESD22-B104C, Mil-Std-883, method 2002, Cond. D, 10,000g's, 0.3ms, ±X,Y,Z – 6 directions, 5 times/direction	3	5	(0/1)
Vibration	JEDEC JESD22-B103B, Variable Frequency (random), Cond. B, 5-500Hz, X,Y,Z – 4 times/direction	3	5	(0/1)
Temperature Cycling ⁽¹⁾	JEDEC JESD22-A104D Condition N, -40°C to +85°C, Soak Mode 2, 100 cycles	3	77	(0/1)

Board Level Tests

TEST	Method/Condition	Lot Quantity	Sample / Lot	Acc / Reject Criteria
Board Mechanical Shock	JEDEC JESD22-B104C, Mil-Std-883, method 2002, Cond. D, 10000g's, 0.3ms, ±X,Y,Z – 6 directions, 5 times/direction	1	5	(0/1)
Board T/C	JEDEC JESD22-A104D Condition N, -40°C to +85°C, Soak Mode 2, 100 cycles	1	40	(0/1)

(1) – Tests are preceded by MSL3 Preconditioning in accordance with JEDEC JESD22-A113F



11 Environmental Compliance

The MPU-30X0 is RoHS and Green compliant.

The MPU-30X0 is in full environmental compliance as evidenced in report HS-MPU-3000A, Materials Declaration Data Sheet.

Environmental Declaration Disclaimer:

InvenSense believes this environmental information to be correct but cannot guarantee accuracy or completeness. Conformity documents for the above component constitutes are on file. InvenSense subcontracts manufacturing and the information contained herein is based on data received from vendors and suppliers, which has not been validated by InvenSense.



MPU-3000/MPU-3050 Product Specification

Document Number: PS-MPU-3000A-00
Revision: 2.5
Release Date: 12/23/2010

This information furnished by InvenSense is believed to be accurate and reliable. However, no responsibility is assumed by InvenSense for its use, or for any infringements of patents or other rights of third parties that may result from its use. Specifications are subject to change without notice. InvenSense reserves the right to make changes to this product, including its circuits and software, in order to improve its design and/or performance, without prior notice. InvenSense makes no warranties, neither expressed nor implied, regarding the information and specifications contained in this document. InvenSense assumes no responsibility for any claims or damages arising from information contained in this document, or from the use of products and services detailed therein. This includes, but is not limited to, claims or damages based on the infringement of patents, copyrights, mask work and/or other intellectual property rights.

Certain intellectual property owned by InvenSense and described in this document is patent protected. No license is granted by implication or otherwise under any patent or patent rights of InvenSense. This publication supersedes and replaces all information previously supplied. Trademarks that are registered trademarks are the property of their respective companies. InvenSense sensors should not be used or sold in the development, storage, production or utilization of any conventional or mass-destructive weapons or for any other weapons or life threatening applications, as well as in any other life critical applications such as medical equipment, transportation, aerospace and nuclear instruments, undersea equipment, power plant equipment, disaster prevention and crime prevention equipment.

InvenSense[™], InstantGesture[™], iG[™], BlurFree[™], AirSign[™], TouchAnywhere[™], and MotionCommand[™], are registered trademarks of InvenSense, Inc., MPU[™], MPU-30X0[™], MPU-3000[™], MPU-3050[™], Motion Processing Unit[™], Digital Motion Processing[™], and DMP[™] are trademarks of InvenSense, Inc.

©2010 InvenSense, Inc. All rights reserved.

